

09936073 24/09/2003

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NEWS	1		Web Page URLs for STN Seminar Schedule - N. America
NEWS	2		"Ask CAS" for self-help around the clock
NEWS	3	SEP 09	CA/CAPLUS records now contain indexing from 1907 to the present
NEWS	4	Jul 15	Data from 1960-1976 added to RDISCLOSURE
NEWS	5	Jul 21	Identification of STN records implemented
NEWS	6	Jul 21	Polymer class term count added to REGISTRY
NEWS	7	Jul 22	INPADOC: Basic index (/BI) enhanced; Simultaneous Left and Right Truncation available
NEWS	8	AUG 05	New pricing for EUROPATFULL and PCTFULL effective August 1, 2003
NEWS	9	AUG 13	Field Availability (/FA) field enhanced in BEILSTEIN
NEWS	10	AUG 15	PATDPAFULL: one FREE connect hour, per account, in September 2003
NEWS	11	AUG 15	PCTGEN: one FREE connect hour, per account, in September 2003
NEWS	12	AUG 15	RDISCLOSURE: one FREE connect hour, per account, in September 2003
NEWS	13	AUG 15	TEMA: one FREE connect hour, per account, in September 2003
NEWS	14	AUG 18	Data available for download as a PDF in RDISCLOSURE
NEWS	15	AUG 18	Simultaneous left and right truncation added to PASCAL
NEWS	16	AUG 18	FROSTI and KOSMET enhanced with Simultaneous Left and Right Truncation
NEWS	17	AUG 18	Simultaneous left and right truncation added to ANABSTR
NEWS	18	SEP 22	DIPPR file reloaded
NEWS	EXPRESS		April 4 CURRENT WINDOWS VERSION IS V6.01a, CURRENT MACINTOSH VERSION IS V6.0b(ENG) AND V6.0Jb(JP), AND CURRENT DISCOVER FILE IS DATED 01 APRIL 2003
NEWS	HOURS		STN Operating Hours Plus Help Desk Availability
NEWS	INTER		General Internet Information
NEWS	LOGIN		Welcome Banner and News Items
NEWS	PHONE		Direct Dial and Telecommunication Network Access to STN
NEWS	WWW		CAS World Wide Web Site (general information)

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Kamal Saeed

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* * * * * STN Columbus * * * * *

FILE 'HOME' ENTERED AT 08:21:14 ON 24 SEP 2003

	SINCE FILE	TOTAL
COST IN U.S. DOLLARS	ENTRY	SESSION
FULL ESTIMATED COST	0.21	0.21

FILE 'REGISTRY' ENTERED AT 08:21:23 ON 24 SEP 2003
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STRUCTURE FILE UPDATES: 22 SEP 2003 HIGHEST RN 591204-55-6
DICTIONARY FILE UPDATES: 22 SEP 2003 HIGHEST RN 591204-55-6

TSCA INFORMATION NOW CURRENT THROUGH JULY 14, 2003

Please note that search-term pricing does apply when
conducting SmartSELECT searches.

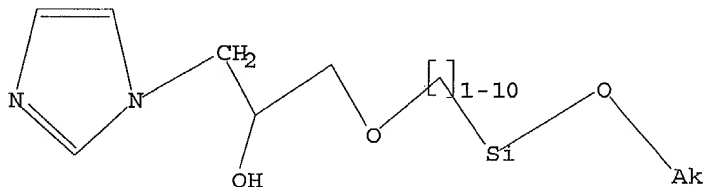
Crossover limits have been increased. See HELP CROSSOVER for details.

Experimental and calculated property data are now available. See HELP
PROPERTIES for more information. See STN Note 27, Searching Properties
in the CAS Registry File, for complete details:
<http://www.cas.org/ONLINE/STN/STNOTES/stnotes27.pdf>

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Uploading 09936073.str

L1 STRUCTURE UPLOADED

=> d
L1 HAS NO ANSWERS
L1 STR



Structure attributes must be viewed using STN Express query preparation.

=> s l1 full
FULL SEARCH INITIATED 08:21:51 FILE 'REGISTRY'
FULL SCREEN SEARCH COMPLETED - 156 TO ITERATE

100.0% PROCESSED	156 ITERATIONS	56 ANSWERS
SEARCH TIME: 00.00.01		

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L2 56 SEA SSS FUL L1

=> file caplus
COST IN U.S. DOLLARS

SINCE FILE	TOTAL
ENTRY	SESSION
148.15	148.36

FULL ESTIMATED COST

FILE 'CAPLUS' ENTERED AT 08:21:58 ON 24 SEP 2003
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FILE COVERS 1907 - 24 Sep 2003 VOL 139 ISS 13
FILE LAST UPDATED: 23 Sep 2003 (20030923/ED)

This file contains CAS Registry Numbers for easy and accurate substance identification.

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L3 33 L2

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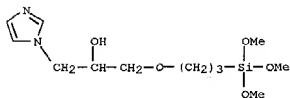
L3 ANSWER 1 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
 ACCESSION NUMBER: 2003:693359 CAPLUS
 DOCUMENT NUMBER: 138:257832
 TITLE: Epoxy resin compositions with good reflow crack resistance and one-side-sealed semiconductor devices
 INVENTOR(S): Sugiyama, Hiroshi; Toyama, Takashi
 PATENT ASSIGNEE(S): Matsushita Electric Works, Ltd., Japan
 SOURCE: Jpn. Kokai Tokkyo Koho, 10 pp.
 CODEN: JKXXAF
 DOCUMENT TYPE: Patent
 LANGUAGE: Japanese
 FAMILY ACC. NUM. COUNT: 1
 PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 2003246839	A2	20030905	JP 2002-48773	20020225
JP 2002-48773			20020225	

PRIORITY APPLN. INFO.:
 AB The comps. comprise (a) epoxy resins contg. XCR2R3-1,4-C6H4CR4R5X (I; X =
 3-R1-4-GO-substituted Ph; G = glycidyl; R1-R5 = H, Me, tert-Bu) and/or
 GO-1,4-C6H4CMe2-1,4-C6H4CMe22 (2 = 4-GO-substituted Ph), (b) crosslinking
 agents contg. phenol novolak HOC6H4[CH2C6H3(OH)]mCH2C6H4OH (II; m
 .gtoreq.0) with II (m = 0) content .ltoreq.10%, (c) crosslinking
 accelerators, and (d) inorg. fillers. Thus, a compn. contg. I (R1-R5 =
 Me) 7.8, DL 92 (II) 4, a reaction product of tetraphenylphosphonium
 tetraphenylborate and II 0.3, and fused silica 86 parts was
 transfer-molded to give a test piece showing Tg 198.degree., low warpage,
 and shrinkage at molding (JIS K 6911) 0.08%.

IT 149394-70-7
 RL: MOA (Modifier or additive use); TEM (Technical or engineered material
 use); USES (Uses)
 (epoxy resin compns. with good reflow crack resistance for
 one-side-sealed semiconductor devices)

RN 149394-70-7 CAPLUS
 CN 1H-Imidazole-1-ethanol, .alpha.-[([3-(trimethoxysilyl)propoxy)methyl]-
 (9CI) (CA INDEX NAME)]



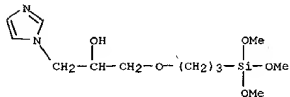
L3 ANSWER 3 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
 ACCESSION NUMBER: 2003:132664 CAPLUS
 DOCUMENT NUMBER: 138:179310
 TITLE: Paper sheet made of fluoropolymer fiber, copper-clad board using the paper sheet for printed circuit, and manufacture of board
 INVENTOR(S): Suzuki, Takanori; Tsuda, Osamu
 PATENT ASSIGNEE(S): Tomoe-gawa Paper Co., Ltd., Japan
 SOURCE: Jpn. Kokai Tokkyo Koho, 8 pp.
 CODEN: JKXXAF
 DOCUMENT TYPE: Patent
 LANGUAGE: Japanese
 FAMILY ACC. NUM. COUNT: 1
 PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 2003049387	A2	20030221	JP 2001-234365	20010802
JP 2001-234365			20010802	

PRIORITY APPLN. INFO.:
 AB The porous sheet is that obtained by paper-making wet process of a slurry
 contg. fluoropolymer fibers optionally assocd. with inorg. fibers and/or
 inorg. particles followed by firing, which has av. pore size 1-50 .mu.m
 and max. pore size .ltoreq.250 .mu.m. The board consists of the paper
 sheet and a Cu foil with 10-point av. surface roughness Rz 0.5-8.0 .mu.m,
 which are laminated and hot pressed in vacuo in the claimed manufg.
 process. The board, showing improved adhesion between the fluoropolymer
 fiber paper and the Cu foil, provides a printed circuit board requiring
 low dielec. loss tangent.

IT 149394-70-7, IS 1000
 RL: MOA (Modifier or additive use); USES (Uses)
 (composers; for porous paper sheet made of fluoropolymer fiber for
 copper-clad printed circuit board)

RN 149394-70-7 CAPLUS
 CN 1H-Imidazole-1-ethanol, .alpha.-[([3-(trimethoxysilyl)propoxy)methyl]-
 (9CI) (CA INDEX NAME)]

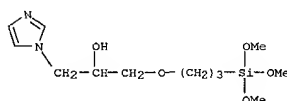


L3 ANSWER 2 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
 ACCESSION NUMBER: 2003:219344 CAPLUS
 DOCUMENT NUMBER: 138:257832
 TITLE: Secondary lithium battery
 INVENTOR(S): Tajima, Ryochi; Kumagaya, Masashi
 PATENT ASSIGNEE(S): Japan Energy Corp., Japan; Kashima Oil Co., Ltd.;
 Nikko Materials Co., Ltd.; Petoca Materials Ltd.
 SOURCE: Jpn. Kokai Tokkyo Koho, 7 pp.
 CODEN: JKXXAF
 DOCUMENT TYPE: Patent
 LANGUAGE: Japanese
 FAMILY ACC. NUM. COUNT: 1
 PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 2003086185	A2	20030320	JP 2001-272213	20010907
JP 2001-272213			20010907	

PRIORITY APPLN. INFO.:
 AB The battery has an anode contg. a Li-intercalating active mass, a
 cathode,
 and an electrolyte; where the anode contains a imidazole silane compd.
 IT 149394-70-7
 RL: DEV (Device component use); USES (Uses)
 (anodes contg. imidazole silane compds. for secondary lithium
 batteries)

RN 149394-70-7 CAPLUS
 CN 1H-Imidazole-1-ethanol, .alpha.-[([3-(trimethoxysilyl)propoxy)methyl]-
 (9CI) (CA INDEX NAME)]



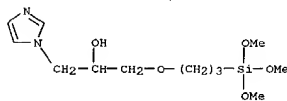
L3 ANSWER 4 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
 ACCESSION NUMBER: 2002:921414 CAPLUS
 DOCUMENT NUMBER: 138:5357
 TITLE: Prepreg made of epoxy resin-impregnated organic fiber substrate and laminated board
 INVENTOR(S): Ishida, Takehiro; Takada, Toshiharu
 PATENT ASSIGNEE(S): Matsushita Electric Works, Ltd., Japan
 SOURCE: Jpn. Kokai Tokkyo Koho, 6 pp.
 CODEN: JKXXAF
 DOCUMENT TYPE: Patent
 LANGUAGE: Japanese
 FAMILY ACC. NUM. COUNT: 1
 PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 2002346392	A2	20021204	JP 2001-159105	20010528
JP 2001-159105			20010528	

PRIORITY APPLN. INFO.:
 AB The prepreg is that obtained by impregnation of an org. fiber substrate
 with a compn. of a P-contg. epoxy resin, a hardener for epoxy resin, and
 a
 imidazolesilane as a surface treatment. The laminated board, preferably a
 metal-clad laminated board as printed circuit board with fire resistance
 and good laser processability (compared with prepreps using glass
 fibers),
 is that prep. by hot pressing of the prepreg. Thus, 9,10-dihydro-9-oxa-
 10-phosphaphenanthrene (HCA) and cresol novolak epoxy resin (YDCN 701)
 were reacted to give P-contg. epoxy resin, 100 parts of which was mixed
 with 39 parts bisphenol A novolak resin (Epicure YLM 129) and 1.0 part
 imidazolesilane (IS 1000) and dissolved in MEK to give a varnish. Then,
 all arom. aramid nonwoven fabrics were impregnated with the varnish to
 give the prepreps, 8 of which were laminated, sandwiched between a pair
 of
 Cu foils, and hot-pressed to give a Cu-clad laminated board showing UL-94
 flame retardance V-0 and blister in heating to 270.degree..

IT 149394-70-7, IS 1000
 RL: MOA (Modifier or additive use); USES (Uses)
 (surface treatment; in prepreg made of epoxy resin-impregnated org.
 fiber substrate for laminated printed circuit board)

RN 149394-70-7 CAPLUS
 CN 1H-Imidazole-1-ethanol, .alpha.-[([3-(trimethoxysilyl)propoxy)methyl]-
 (9CI) (CA INDEX NAME)]

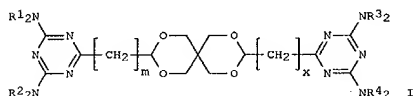


09936073 24/09/2003

L3 ANSWER 5 OF 33 CAPLUS COPYRIGHT 2003 ACS ON STN
 ACCESSION NUMBER: 2002:592037 CAPLUS
 DOCUMENT NUMBER: 137:155781
 TITLE: Epoxy resin compositions and optical semiconductor devices sealed with them
 INVENTOR(S): Nakasuiji, Ikuo; Yamahaka, Hiroshi
 PATENT ASSIGNEE(S): Matsushita Electric Works, Ltd., Japan
 SOURCE: Jpn. Kokai Tokkyo Koho, 10 pp.
 CODEN: JKXXAF
 DOCUMENT TYPE: Patent
 LANGUAGE: Japanese
 FAMILY ACC. NUM. COUNT: 1
 PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 2002220512	A2	20020809	JP 2001-17712	20010126

PRIORITY APPLN. INFO.: JP 2001-17712 20010126
 OTHER SOURCE(S): MARPAT 137:155781
 GI



AB The compns., showing good adhesion to Pd- or Pd-Au-plated lead frames, contain epoxy resins (A), acid anhydride curing agents (B), mold-releasing agents (C), N compds. (D) selected from R2NC:NR1HC.tplbond.N (R = H, Cl-10 hydrocarbyl, benzothiazole-2-thiol, 1H-benzimidazole-2-thiol, I (R1-4 = same as R; m, x = 1-10), R5R6NC:SSC:SNR7R8 (R5-8 = same as R), and SCH2CH(OH)CH2O(CH2)2SiR93-n(OR10)n (Y = Cl-10 hydrocarbyl-(un)substituted 1-imidazolyl; R9,10 = Cl-10 hydrocarbyl; n = 1-3; z = 1-10), and optionally SH-contg. Si compds. (E) HSR11SiR123-n'(OR13)n' (R11 = Cl-10 hydrocarbylene; R12,13 = Cl-10 hydrocarbyl; n' = 1-3). The semiconductor devices, (e.g., light-emitting diodes, laser diodes, photodiodes, phototransistors), sealed with the compns. show good light transmittance and moisture resistance.
 IT 149394-70-7D, derivs.
 RL: MOA (Modifier or additive use); TEM (Technical or engineered material use); USES (Uses)
 (epoxy resin compns. contg. acid anhydrides, N compds., and SH-contg. Si compds. for sealing optical semiconductor devices)
 RN 149394-70-7 CAPLUS
 CN 1H-Imidazole-1-ethanol, .alpha.-[3-(trimethoxysilyl)propoxy)methyl]- (9CI) (CA INDEX NAME)

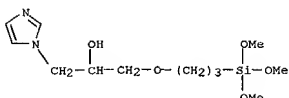
L3 ANSWER 6 OF 33 CAPLUS COPYRIGHT 2003 ACS ON STN
 ACCESSION NUMBER: 2002:592036 CAPLUS
 DOCUMENT NUMBER: 137:125891
 TITLE: Epoxy potting composition for semiconductor device with good adhesion
 INVENTOR(S): Sawai, Akito
 PATENT ASSIGNEE(S): Matsushita Electric Works, Ltd., Japan
 SOURCE: Jpn. Kokai Tokkyo Koho, 9 pp.
 CODEN: JKXXAF
 DOCUMENT TYPE: Patent
 LANGUAGE: Japanese
 FAMILY ACC. NUM. COUNT: 1
 PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 2002220511	A2	20020809	JP 2001-16461	20010125

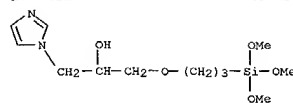
PRIORITY APPLN. INFO.: JP 2001-16461 20010125
 OTHER SOURCE(S): MARPAT 137:125891
 GI

* STRUCTURE DIAGRAM TOO LARGE FOR DISPLAY - AVAILABLE VIA OFFLINE PRINT *

AB The compn. comprises an epoxy resin, a phenolic resin, a curing accelerator, an inorg. filler, a release agent, and an imidazole silane selected from I, II, and/or III (R1 = H, vinyl, Cl-5 alkyl; R2 = H, Cl-20 alkyl; R3, R4 = Cl-3 alkyl; n = 1-3 integer). Thus, a compn. was made from a mixt. of ESCN 195XL 8.1, ESB 400T 1.3, FSM 6200 4.5, triphenylphosphine 0.1, SE203 1.4, polyethylene wax 0.2, C black 0.2, cryst. SiO2 82, KRM 403 0.2, and IA 100 2.0%.
 IT 149394-70-7, IS 1000
 RL: MOA (Modifier or additive use); USES (Uses)
 (epoxy potting compn. for semiconductor device with good adhesion)
 RN 149394-70-7 CAPLUS
 CN 1H-Imidazole-1-ethanol, .alpha.-[3-(trimethoxysilyl)propoxy)methyl]- (9CI) (CA INDEX NAME)



L3 ANSWER 5 OF 33 CAPLUS COPYRIGHT 2003 ACS ON STN (Continued)

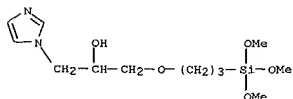


L3 ANSWER 7 OF 33 CAPLUS COPYRIGHT 2003 ACS ON STN
 ACCESSION NUMBER: 2002:344954 CAPLUS
 DOCUMENT NUMBER: 136:341854
 TITLE: Epoxy resin compositions with good moisture resistance and adhesion to palladium and gold, and semiconductor devices sealed with them
 INVENTOR(S): Shiraki, Hiroyuki; Nakamura, Masashi; Tsuji, Takayuki
 PATENT ASSIGNEE(S): Matsushita Electric Works, Ltd., Japan
 SOURCE: Jpn. Kokai Tokkyo Koho, 7 pp.
 CODEN: JKXXAF
 DOCUMENT TYPE: Patent
 LANGUAGE: Japanese
 FAMILY ACC. NUM. COUNT: 1
 PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 2002128872	A2	20020509	JP 2000-325000	20001025

PRIORITY APPLN. INFO.: JP 2000-325000 20001025

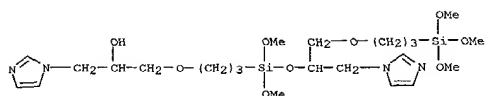
AB The compns. comprise epoxy resins, phenolic resins, inorg. fillers, and 0.001-2.0% imidazole silanes having no direct linkage between Si and N. Thus, a compn. comprising o-cresol-formaldehyde novolak epoxy resin (ESCN 195XL), dicyclopentadiene-phenol-based epoxy resin (HP 7200), aralkyl phenolic resin (HE 100), and imidazole silanes showed adhesion strength to Pd and Pd/Au, 11.0 and 10.3 MPa, resp., and good reflow resistance in packaging semiconductor devices.
 IT 149394-70-7 149394-84-3 187463-05-4 187463-07-6
 RL: MOA (Modifier or additive use); TEM (Technical or engineered material use); USES (Uses)
 (imidazole silane-contg. epoxy resin compns. with good moisture resistance and adhesion to Pd and Au for semiconductor devices packaging)
 RN 149394-70-7 CAPLUS
 CN 1H-Imidazole-1-ethanol, .alpha.-[3-(trimethoxysilyl)propoxy)methyl]- (9CI) (CA INDEX NAME)



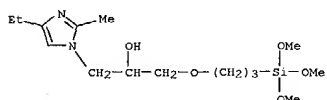
RN 149394-84-3 CAPLUS
 CN 1H-Imidazole-1-ethanol, .alpha.-[8-(1H-imidazol-1-ylmethyl)-6,6,14,14-tetramethoxy-2,7,10,15-tetraoxa-6,14-disilahehexadec-1-yl]- (9CI) (CA INDEX NAME)

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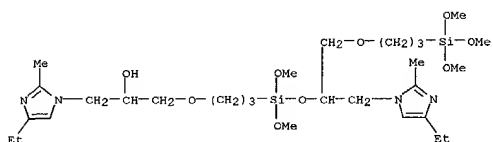
L3 ANSWER 7 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)



RN 187463-05-4 CAPLUS
CN 1H-Imidazole-1-ethanol, 4-ethyl-2-methyl-.alpha.-[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



RN 187463-07-6 CAPLUS
CN 1H-Imidazole-1-ethanol, 4-ethyl-2-methyl-.alpha.-[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



L3 ANSWER 9 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 2001:840573 CAPLUS
DOCUMENT NUMBER: 135:373067
TITLE: Coupling agent-containing anticorrosive epoxy composition for coating metal surface
INVENTOR(S): Tsuchida, Katsuyuki; Kumagaya, Masashi
PATENT ASSIGNEE(S): Nikko Materials Co., Ltd., Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 6 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

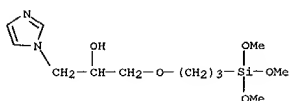
PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 2001316835	A2	20011116	JP 2000-129547	20000428

PRIORITY APPLN. INFO.: JP 2000-129547 20000428

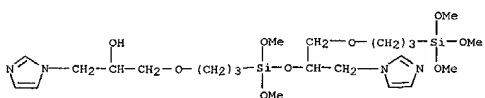
AB Title coating compn. comprises a redative mixt. of epoxy resins and phosphoric compds. or esters and silane or titanium coupling agents. Thus, a galvanized steel plate was coated with a compn. comprising phosphoric acid-modified Epikote 828, 3.5, imidazole silanes 1, and melamine resin 3.5 parts, showing good anticorrosion.

IT 149394-70-7 149394-84-3
RL: MOA (Modifier or additive use); USES (Uses)
(prepn. of coupling agent-contg. anticorrosive epoxy compn. for coating metal surface)

RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



RN 149394-84-3 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



L3 ANSWER 8 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 2001:900692 CAPLUS
DOCUMENT NUMBER: 136:41233
TITLE: Surface treating agents of aluminum and aluminum alloy
INVENTOR(S): for improving corrosion resistance and adhesion of coating films after painting
Izumi, Koichiro; Nishimura, Satoshi; Tauge, Kunji; Miyamoto, Satoshi
PATENT ASSIGNEE(S): Honda Motor Co., Ltd., Japan; Nippon Paint Co., Ltd.
SOURCE: Jpn. Kokai Tokkyo Koho, 6 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

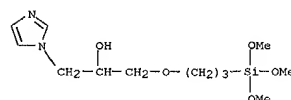
PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 2001342578	A2	20011214	JP 2000-162585	20000531

PRIORITY APPLN. INFO.: JP 2000-162585 20000531

AB The surface treating agents contain a carboxyl group-contg. polymer 0.06-3, a Zr compd. 0.07-3.6 (as Zr), optionally substituted imidazole 0.03-2.4, amino-modified silicone 0.03-2.4, and optionally HF 0.01-14. The Al and Al alloy are used for automobiles.

IT 149394-70-7, IS-1000
RL: TEM (Technical or engineered material use); USES (Uses)
(surface treating agents of aluminum and aluminum alloy for improving corrosion resistance and adhesion of coating films after painting)

RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



L3 ANSWER 10 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 2001:763007 CAPLUS
DOCUMENT NUMBER: 135:319286
TITLE: Monocarboxylate salts of imidazole reaction products, process for preparing the salts, and surface treatments, additives for resins, and resin compositions, containing the same
INVENTOR(S): Kumagai, Masashi; Tsuchida, Katsuyuki
PATENT ASSIGNEE(S): Nikko Materials Co., Ltd., Japan
SOURCE: PCT Int. Appl., 23 pp.
CODEN: PIXXD2
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
WO 2001077119	A1	20011018	WO 2001-JP819	20010206

W: CN, KR, US
RW: AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, TR

JP 2001348393 A2 20011218 JP 2000-226757 20000727
EP 1277757 A1 20030122 EP 2001-902777 20010206
R: AE, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, FI, CY, TR

US 2003088108 A1 20030508 US 2001-936073 20010905
JP 2000-106274 A 20000407
JP 2000-226757 A 20000727
WO 2001-JP819 W 20010206

PRIORITY APPLN. INFO.: JP 2000-106274 A 20000407
JP 2000-226757 A 20000727
WO 2001-JP819 W 20010206

OTHER SOURCE(S): MARPAT 135:319286

AB Imidazoles react with glycidoxypolytrimethoxysilane compds. at 80.degree.-200.degree. and monocarboxylic acids at 50.degree.-200.degree. to prep. adhesion promoters. Thus, imidazole was added to the epoxy group of 3-glycidoxypolytrimethoxysilane, used to form a salt with methacrylic acid. The salt improved adhesion of an epoxy resin to an Al alloy.

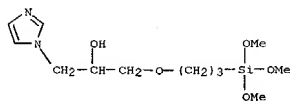
IT 367523-05-5F 367523-06-6P
RL: IMF (Industrial manufacture); MOA (Modifier or additive use); PREP (Preparation); USES (Uses)
(monocarboxylate salts of imidazole reaction products for surface treatments and additives for resins)

RN 367523-05-5 CAPLUS
CN 2-Propenoic acid, 2-methyl-, compd. with .alpha.-[3-(trimethoxysilyl)propoxy]methyl]-1H-imidazole-1-ethanol (1:1) (9CI) (CA INDEX NAME)

CM 1
CRN 149394-70-7
CMF C12 H24 N2 O5 Si

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L3 ANSWER 10 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)



CM 2

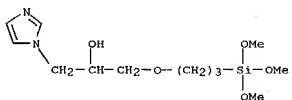
CRN 79-41-4
CMF C4 H6 O2



RN 367523-06-6 CAPLUS
CN Hexadecanoic acid, compd. with
.alpha.-[3-(trimethoxysilyl)propoxy]methyl
]-1H-imidazole-1-ethanol (1:1) (9CI) (CA INDEX NAME)

CM 1

CRN 149394-70-7
CMF C12 H24 N2 O5 Si



CM 2

CRN 57-10-3
CMF C16 H32 O2

HO2C--(CH2)14-Me

IT 149394-70-7P
RL: IMF (Industrial manufacture); RCT (Reactant); PREP (Preparation);
RACT

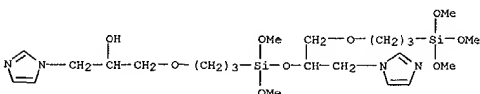
L3 ANSWER 11 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN

ACCESSION NUMBER: 2001:717394 CAPLUS
DOCUMENT NUMBER: 135:274270
TITLE: The metal surface treatment solution containing
silane coupling agent and metals coated with the treatment
solution
INVENTOR(S): Tsuchida, Katsuyuki; Kumagaya, Masashi
PATENT ASSIGNEE(S): Nikko Materials Co., Ltd., Japan
SOURCE: Jpn. Kokai Tokyo Koho, 8 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 2001271185	A2	20011002	JP 2000-86427	20000327
PRIORITY APPL. INFO.:			JP 2000-86427	20000327

OTHER SOURCE(S): MARPAT 135:274270
AB An alk. corrosion inhibiting metal surface treatment soln. contains silicic acid, an amine and a silane deriv. selected from R1Si(OR2)nR33-n (R1 = hydrocarbyl group substituted with epoxy, vinyl, methacryl, amino, mercapto, imidazolyl, halo, styryl, or acryl groups; R2, R3 = Cl-5 alkyl; R1-3 may contain ether bond) and Si(OR4)4 (R4 = Cl-5 alkyl). The coating compn. may also contain water-sol. resins. Metals treated with the soln. exhibit excellent corrosion resistance and bonding with resin coatings.

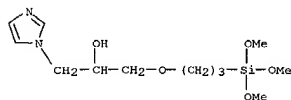
IT 149394-84-3 364042-36-4
RL: NUU (Other use, unclassified); USES (Uses)
(anticorrosive aq. coating compn. contg. silane coupling agents)
RN 149394-84-3 CAPLUS
CN 1H-imidazole-1-ethanol, .alpha.-[8-(1H-imidazol-1-ylmethyl)-6,6,14,14-tetramethoxy-2,7,10,15-tetraoxa-6,14-disilahehexadec-1-yl]- (9CI) (CA INDEX NAME)



RN 364042-36-4 CAPLUS
CN 1H-imidazole-1-ethanol, .alpha.-[2-(trimethoxysilyl)ethoxy]methyl]- (9CI)
(CA INDEX NAME)

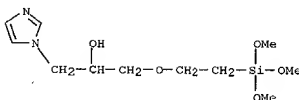
L3 ANSWER 10 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)

(Reactant or reagent)
(monocarboxylate salts of imidazole reaction products for surface treatments and additives for resins)
RN 149394-70-7 CAPLUS
CN 1H-imidazole-1-ethanol, .alpha.-[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



REFERENCE COUNT: 5 THERE ARE 5 CITED REFERENCES AVAILABLE FOR THIS RECORD. ALL CITATIONS AVAILABLE IN THE RE FORMAT

L3 ANSWER 11 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)



09936073 24/09/2003

L3 ANSWER 12 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 2001:507896 CAPLUS
DOCUMENT NUMBER: 135:56160
TITLE: Method for metal plating, pre-treating agent, and semiconductor wafer and semiconductor device using the same
INVENTOR(S): Imori, Toru; Kumagaya, Masashi; Sekiguchi, Junnosuke
PATENT ASSIGNEE(S): Nikko Materials Co., Ltd., Japan
SOURCE: PCT Int. Appl., 23 pp.
CODEN: PIXXD2
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

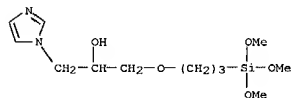
PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
WO 2001049898	A1	20010712	WO 2000-JP8166	20001120
W: CN, JP, KR, US RW: DE, FR, GB, IT				
PRIORITY APPLN. INFO.: JP 2000-1645 A 20000107 JP 2000-238047 A 20000807				

AB A method for metal plating which comprises admixing or reacting a noble metal compd. as a catalyst with a silane coupling agent contg. a functional group having the capability of capturing a metal, to thereby prep. a pre-treating agent, subjecting an article to be treated to the surface treatment with the pre-treating agent, and then subjecting the pre-treated article to electroless plating. The method permits the

prep. without fail of metal-plated products also from a powder, a resin cloth and an article having a mirror surface such as a semiconductor wafer, which have been difficult to be metal-plated conventionally. Moreover, the employment of the method in fine wiring on the surface of a semiconductor wafer leads to the satisfactory coverage of a seed layer onto the inner wall of a via trench. As the silane coupling agent, a compd. having an azole group, in particular, imidazole group is suitably used.

IT 149394-70-7
RL: NUU (Other use, unclassified); USES (Uses)
(coupling agent; method for metal plating, pre-treating agent, and semiconductor wafer and semiconductor device using the same)

RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



L3 ANSWER 13 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 2001:495296 CAPLUS
DOCUMENT NUMBER: 135:93601
TITLE: Silane additives, storage-stable epoxy resin compositions containing them with excellent curability, and their use
INVENTOR(S): Tsuchida, Katsuyuki; Kumagaya, Masashi
PATENT ASSIGNEE(S): Nikko Materials Co., Ltd., Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 7 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

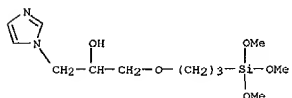
PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 2001187836	A2	20010710	JP 2001-39712	20010216
PRIORITY APPLN. INFO.: JP 2001-39712 20010216				
OTHER SOURCE(S): MARPAT 135:93601				

AB The additives, useful for sealants, resists, coatings, primers, and printed circuit boards, are QCH2CH(OH)CH2OCH2CH2CH2Si(OR3)2R4 [I; Q = 2-R1-4-R2-imidazolyl-1-yl; R1 = H, vinyl, C1-5 alkyl; R2 = H, C1-20 alkyl;

R3,4 = C1-3 alkyl) or Me2NCH2CH(OH)CH2OCH2CH2CH2Si(OR3)2R4 (R3,4 = same as above). Thus, 2 sheets of A 2024P (Al alloy plate) were laminated via a 100:5:1:1 mixt. of Epikote 828 (bisphenol A epoxy resin), AH 154 (dicyandiamide), 2-methyl-4-methylimidazole, and I (R1,2 = H; R3 = Et; R4 = Me) to give a test piece with shear strength 1.13 kN/cm2.

IT 149394-70-7 348077-93-0
RL: MOA (Modifier or additive use); USES (Uses)
(storage-stable epoxy resin compns. contg. imidazol- or dimethylamino-contg. silane additives for sealants, resists, coatings, and printed circuit boards)

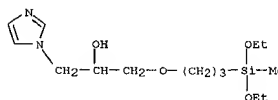
RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



RN 348077-93-0 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(diethoxymethylsilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)

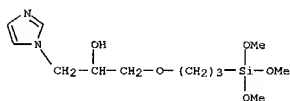
L3 ANSWER 12 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)
REFERENCE COUNT: 12 THERE ARE 12 CITED REFERENCES AVAILABLE FOR THIS RECORD. ALL CITATIONS AVAILABLE IN THE RE
FORMAT

L3 ANSWER 13 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)



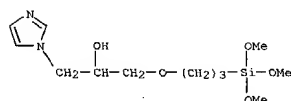
09936073 24/09/2003

L3 ANSWER 14 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
 ACCESSION NUMBER: 2000:385771 CAPLUS
 DOCUMENT NUMBER: 133:322674
 TITLE: Improved adhesion between polyimide film and copper metal
 AUTHOR(S): Inagaki, Norihiro; Tasaka, Shigeru; Sobukawa, Tadashi;
 CORPORATE SOURCE: Tamura, Katsuhiro
 SOURCE: Faculty of Engineering, Shizuoka University, Japan
 (1999), 37th, 45-48
 CODEN: KYNTTX
 PUBLISHER: Nippon Setchaku Gakkai
 DOCUMENT TYPE: Journal
 LANGUAGE: Japanese
 AB Polyimide film (Kapton 200H) surface-modified by vinylimidazole plasma graft polym. or silane coupling reaction with 1-[2-hydroxy-3-[[3-(trimethoxysilyl)propyl]]-1,3-diazole showed improved adhesion to Cu, and the contribution of the imidazole group introduced into the polyimide surface to the adhesive strength improvement is large.
 IT 149394-70-7
 RL: MOA (Modifier or additive use); USES (Uses)
 (Improved adhesion between polyimide film and copper metal)
 RN 149394-70-7 CAPLUS
 CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



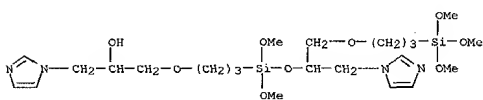
L3 ANSWER 15 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
 ACCESSION NUMBER: 2000:376949 CAPLUS
 DOCUMENT NUMBER: 133:5927
 TITLE: Anticorrosive coating compositions and corrosion-resistant metal sheets coated therewith
 INVENTOR(S): Akutsu, Yoshinori
 PATENT ASSIGNEE(S): Japan Energy K. K., Japan
 SOURCE: Jpn. Kokai Tokkyo Koho, 6 pp.
 CODEN: JKXXAP
 DOCUMENT TYPE: Patent
 LANGUAGE: Japanese
 FAMILY ACC. NUM. COUNT: 1
 PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 2000154349	A2	20000606	JP 1998-331107	19981120
PRIORITY APPLN. INFO.:			JP 1998-331107	19981120
OTHER SOURCE(S):		MARPAT 133:5927		
AB	The comps. with excellent adhesion to metal sheets comprise (A) organosilicon compds. having imidazole and alkoxyisilyl groups, (B) epoxy resins having .gtorog.2 epoxy groups in a mol., and (C) organosilicon compds. having 3 carbonyl and alkoxyisilyl groups, or (D) H2O-insol. organosilicon compds. having 2 alkoxyisilyl groups. Thus, Epikote 828 10, an imidazole-contg. alkoxyisilane compd. mixt. 1, salicylic acid 0.6, and AcCH[CO(CH2)10Si(OMe)3]CO2(CH2)2Si(OMe)3 2 parts were dissolved in MeOH to give a compn., which was applied on an Al sheet and baked to form a coating showing excellent adhesion and corrosion resistance.			
IT	149394-70-7 149394-84-3 RL: PRP (Properties); TEM (Technical or engineered material use); USES (Uses) (epoxy resin-alkoxyisilane anticorrosive coating compns. with good adhesion to metals)			
RN	149394-70-7 CAPLUS			
CN	1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)			



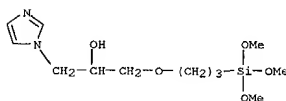
RN 149394-84-3 CAPLUS
 CN 1H-Imidazole-1-ethanol, .alpha.-[8-(1H-imidazol-1-ylmethyl)-6,6,14,14-tetramethoxy-2,7,10,15-tetraoxa-6,14-disilaheptadec-1-yl]- (9CI) (CA INDEX NAME)

L3 ANSWER 15 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)



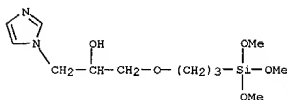
L3 ANSWER 16 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
 ACCESSION NUMBER: 2000:317083 CAPLUS
 DOCUMENT NUMBER: 132:335873
 TITLE: Epoxy resin-based alkoxy silane-containing anticorrosive coating compositions
 INVENTOR(S): Akutsu, Yoshitoku; Kiheida, Yukinori
 PATENT ASSIGNEE(S): Japan Energy K. K., Japan
 SOURCE: Jpn. Kokai Tokkyo Koho, 5 pp.
 CODEN: JKXXAP
 DOCUMENT TYPE: Patent
 LANGUAGE: Japanese
 FAMILY ACC. NUM. COUNT: 1
 PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 2000136344	A2	20000516	JP 1998-311016	19981030
JP 3335932	B2	20021021		
PRIORITY APPLN. INFO.:			JP 1998-311016	19981030
AB	The title compns., useful for refinery plants, tanks, bridges, etc. (no data), comprise epoxy resins (e.g., Epikote 828), amine hardeners (e.g., diaminodicyclohexylmethane), fillers (e.g., silica), and alkoxy silanes (e.g., tetramethoxysilane, IS-1000, LS-3750).			
IT	149394-70-7, IS-1000 RL: PRP (Properties); TEM (Technical or engineered material use); USES (Uses) (IS-1000, coupling agents; epoxy resin-based alkoxy silane-contg. anticorrosive coating compns.)			
RN	149394-70-7 CAPLUS			
CN	1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)			



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L3 ANSWER 17 OF 33 CAPLUS COPYRIGHT 2003 ACS on STM
 ACCESSION NUMBER: 1999:433076 CAPLUS
 DOCUMENT NUMBER: 131:200910
 TITLE: Improved adhesion between Kapton film and copper metal
 AUTHOR(S): by silane-coupling reactions
 CORPORATE SOURCE: Inagaki, N.; Tasaka, S.; Onodera, A.
 Laboratory of Polymer Chemistry, Faculty of Engineering, Shizuoka University, Hamamatsu, 432-8561, Japan
 SOURCE: Journal of Applied Polymer Science (1999), 73(9), 1645-1654
 CODEN: JAPNAB; ISSN: 0021-8995
 PUBLISHER: John Wiley & Sons, Inc.
 DOCUMENT TYPE: Journal
 LANGUAGE: English
 AB Kapton film, poly[(N,N'-oxydiphenylene)pyromellitimide], was modified by silane-coupling reactions using 3'-(trimethoxysilyl)propoxy-2-hydroxypropyl-1,3-diazole (Si-imidazole) to improve the adhesion with copper metal. The Kapton film surface was first treated with argon plasma for 30 s, then dipped into a methanol soln. of Si-imidazole (0.01 wt. %), followed by heating at 110 degrees C for 90 min. The Kapton surfaces, modified by the argon plasma and Si-imidazole coupling reactions, were analyzed by water contact-angle measurement, at. force microscopy, and XPS. The Si-imidazole modification showed a large increase in adhesion between the copper metal and the Kapton film. The peel strength of the copper metal/Kapton film joint increased from 0.94 to 2.4 N/5 mm. The failure occurred at the interface between the Si-imidazole and the Kapton film layer. We conclude that the Si-imidazole modification is an effective treatment for improvement of the adhesion between copper metal and Kapton film.
 IT 149394-70-7
 RL: MOD (Modifier or additive use); RCT (Reactant); RACT (Reactant or reagent); USES (Uses)
 (surface modifier; improved adhesion between Kapton film and copper metal by silane-coupling reactions)
 RN 149394-70-7 CAPLUS
 CN 1H-Imidazole-1-ethanol, .alpha.-[3-(trimethoxysilyl)propoxy)methyl]-(9CI) (CA INDEX NAME)

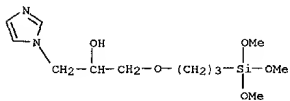


REFERENCE COUNT: 10 THERE ARE 10 CITED REFERENCES AVAILABLE FOR THIS RECORD. ALL CITATIONS AVAILABLE IN THE RS FORMAT

L3 ANSWER 18 OF 33 CAPLUS COPYRIGHT 2003 ACS on STM
 ACCESSION NUMBER: 1999:78681 CAPLUS
 DOCUMENT NUMBER: 130:161885
 TITLE: Manufacture of polyimide-metal composite thin film
 INVENTOR(S): Suzuki, Takanori
 PATENT ASSIGNEE(S): Tomoe-gawa Paper Co., Ltd., Japan
 SOURCE: Jpn. Kokai Tokkyo Koho, 6 pp. CODEN: JKXXAF
 DOCUMENT TYPE: Patent
 LANGUAGE: Japanese
 FAMILY ACC. NUM. COUNT: 1
 PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 11029852	A2	19990202	JP 1997-205349	19970714
JP 3331153	B2	20021007		

PRIORITY APPLN. INFO.: JP 1997-205349 19970714
 AB The manuf. method involves (1) plasma treating a polyimide film surface, (2) treating the film with an imidazole group-contg. silane coupling agent, and (3) forming a metal thin film on the polyimide film by sputtering or deposition. The film shows good adhesion.
 IT 149394-70-7, IS 1000
 RL: NUU (Other use, unclassified); USES (Uses)
 (treatment by plasma and coupling agent in manuf. of polyimide-metal composite film)
 RN 149394-70-7 CAPLUS
 CN 1H-Imidazole-1-ethanol, .alpha.-[3-(trimethoxysilyl)propoxy)methyl]-(9CI) (CA INDEX NAME)

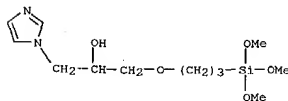


L3 ANSWER 17 OF 33 CAPLUS COPYRIGHT 2003 ACS on STM (Continued)

L3 ANSWER 19 OF 33 CAPLUS COPYRIGHT 2003 ACS on STM
 ACCESSION NUMBER: 1998:768318 CAPLUS
 DOCUMENT NUMBER: 130:74947
 TITLE: Copper foil for printed circuit board
 INVENTOR(S): Tsuchida, Katsuyuki; Kumagaya, Masashi; Okazaki, Yoshinori
 PATENT ASSIGNEE(S): Japan Energy K. K., Japan; Nikko Gould Foil K. K.
 SOURCE: Jpn. Kokai Tokkyo Koho, 15 pp. CODEN: JKXXAF
 DOCUMENT TYPE: Patent
 LANGUAGE: Japanese
 FAMILY ACC. NUM. COUNT: 1
 PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 10317159	A2	19981202	JP 1997-147070	19970522

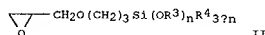
PRIORITY APPLN. INFO.: JP 1997-147070 19970522
 AB The foil has coating of coupling agent having .gtoreq.1 functional groups selected from imidazole, dialkylamino, and pyridine at least on its roughened surface. The foil may have siloxane layer beneath the coupling agent layer. The foil shows strong adhesion with polymer.
 IT 149394-70-7
 RL: DEV (Device component use); USES (Uses)
 (coupling agent; copper foil having coupling agent coatings for stronger adhesion with polymer for printed circuit board)
 RN 149394-70-7 CAPLUS
 CN 1H-Imidazole-1-ethanol, .alpha.-[3-(trimethoxysilyl)propoxy)methyl]-(9CI) (CA INDEX NAME)



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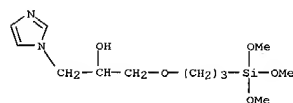
L3 ANSWER 20 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
 ACCESSION NUMBER: 1998:455475 CAPLUS
 DOCUMENT NUMBER: 129:168105
 TITLE: Photosensitive resin composition containing imidazolesilane compound and photosensitive element using same
 INVENTOR(S): Ichikawa, Tatsuya; Tanaka, Yoji; Chiba, Tatsuo; Tsuchita, Katsushi; Kumagaya, Masashi
 PATENT ASSIGNEE(S): Hitachi Chemical Co., Ltd., Japan; Japan Energy K. K.
 SOURCE: Jpn. Kokai Tokkyo Koho, 7 pp.
 CODEN: JRXAXF
 DOCUMENT TYPE: Patent
 LANGUAGE: Japanese
 FAMILY ACC. NUM. COUNT: 1
 PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 10186657	A2	19980714	JP 1996-349441	19961227
PRIORITY APPLN. INFO.: JP 1996-349441 19961227				
OTHER SOURCE(S): MARPAT 129:168105				

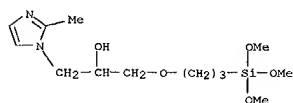


AB The title compn. contains (a) a carboxyl group-contg. binder polymer, (b) a photopolymer compd. having polymerizable ethylenic unsatd. bonds in its mol., (c) a photopolymer initiator, and (d) an imidazolesilane compd. prepd. by reacting an imidazole compd. I (R1 = H or Cl-20 alkyl; R2 = H, vinyl, Cl-5 alkyl) with a silane compd. II (R3, R4 = Cl-3 alkyl; n = 1-3) at 80-200 degree.. The photosensitive element comprises a support coated with a photosensitive layer made of the compn. and optionally laminated with a protective film. The compn. shows good adhesion to metallic substrates, resistance to plating, esp. Au-plating, and chem. resistance.
 IT 149394-70-7P 149394-71-8P 149394-72-9P
 149394-73-0P 149394-84-3P 149394-85-4P
 149394-86-5P 149394-87-6P
 RL: MOA (Modifier or additive use); PNU (Preparation, unclassified); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses) (photosensitive resin compn. contg. imidazolesilane compd.)
 RN 149394-70-7 CAPLUS
 CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)

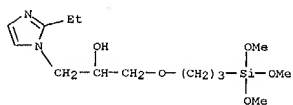
L3 ANSWER 20 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)



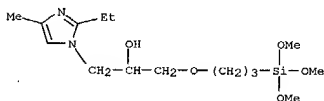
RN 149394-71-8 CAPLUS
 CN 1H-Imidazole-1-ethanol, 2-methyl-.alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



RN 149394-72-9 CAPLUS
 CN 1H-Imidazole-1-ethanol, 2-ethyl-.alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)

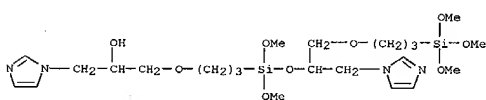


RN 149394-73-0 CAPLUS
 CN 1H-Imidazole-1-ethanol, 2-ethyl-4-methyl-.alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)

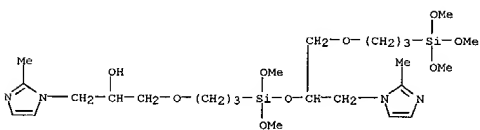


RN 149394-84-3 CAPLUS

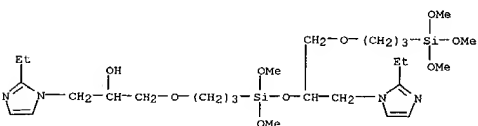
L3 ANSWER 20 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)
 CN 1H-Imidazole-1-ethanol, .alpha.-[[8-[[1H-imidazol-1-ylmethyl]-6,6,14,14-tetramethoxy-2,7,10,15-tetraoxa-6,14-disilahehexadec-1-yl]- (9CI) (CA INDEX NAME)



RN 149394-85-4 CAPLUS
 CN 1H-Imidazole-1-ethanol, 2-methyl-.alpha.-[[6,6,14,14-tetramethoxy-8-[[2-methyl-1H-imidazol-1-ylmethyl]-2,7,10,15-tetraoxa-6,14-disilahehexadec-1-yl]- (9CI) (CA INDEX NAME)

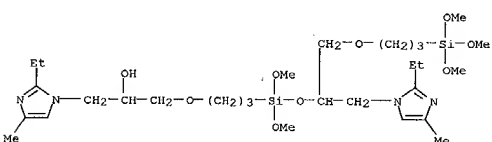


RN 149394-86-5 CAPLUS
 CN 1H-Imidazole-1-ethanol, 2-ethyl-.alpha.-[[8-[[2-ethyl-1H-imidazol-1-ylmethyl]-6,6,14,14-tetramethoxy-2,7,10,15-tetraoxa-6,14-disilahehexadec-1-yl]- (9CI) (CA INDEX NAME)



RN 149394-87-6 CAPLUS
 CN 1H-Imidazole-1-ethanol, 2-ethyl-4-methyl-.alpha.-[[8-[[2-ethyl-4-methyl-1H-imidazol-1-ylmethyl]-6,6,14,14-tetramethoxy-2,7,10,15-tetraoxa-6,14-disilahehexadec-1-yl]-4-methyl- (9CI) (CA INDEX NAME)

L3 ANSWER 20 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)



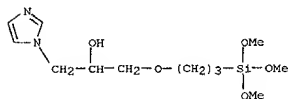
09936073 24/09/2003

L3 ANSWER 21 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
 ACCESSION NUMBER: 1998:407634 CAPLUS
 DOCUMENT NUMBER: 129:123866
 TITLE: Anticorrosive electrodeposition compositions with good
 INVENTOR(S): adhesion to metals
 PATENT ASSIGNEE(S): Akutsu, Yoshinori
 SOURCE: Japan Energy K. K., Japan
 CODEN: JKXXAF
 DOCUMENT TYPE: Patent
 LANGUAGE: Japanese
 FAMILY ACC. NUM. COUNT: 1
 PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 10169355	A2	19980623	JP 1996-326757	19961206
PRIORITY APPL. INFO.:			JP 1996-326757	19961206
OTHER SOURCE(S):		MARPAT 129:123866		

* STRUCTURE DIAGRAM TOO LARGE FOR DISPLAY - AVAILABLE VIA OFFLINE PRINT *

AB Title aq. dispersion compns. contain imidazole silanes I, II, and/or III (R1 = H, vinyl, Cl-5 alkyl; R2 = H, Cl-20 alkyl; R3, R4 = Cl-3 alkyl; n = 1-3) at a preferable amt. of 0.1-10%. A galvanized steel plate was electrodeposited with a mixt. of 500 parts 20% dimethylaminoethyl methacrylate-2-hydroxyethyl acrylate-Me acrylate-styrene-TDI copolymer acetate and 500 parts 2% 5:2:3 I/II/III (R1, R2 = H, R3 = Me, n = 3) blend and baked to form a 20-.mu.m film showing good adhesion to the steel plate initially and after 3 h in boiling water and good corrosion resistance.
 IT 149394-70-7 149394-84-3
 RL: MOA (Modifier or additive use); USES (Uses) (imidazole silane-contg. electrodepositions with metal adhesion and anticorrosion improvement)
 RN 149394-70-7 CAPLUS
 CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]-(9CI) (CA INDEX NAME)



RN 149394-84-3 CAPLUS

L3 ANSWER 22 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
 ACCESSION NUMBER: 1998:289617 CAPLUS
 DOCUMENT NUMBER: 129:16125
 TITLE: Preparation of storage-stable silicon-containing quaternary imidazolium salts, hardening of epoxy resins using them, and their uses
 INVENTOR(S): Tsuchida, Katsuyuki; Kumagaya, Masashi
 PATENT ASSIGNEE(S): Japan Energy K. K., Japan
 SOURCE: Jpn. Kokai Tokkyo Koho, 22 pp.
 CODEN: JKXXAF
 DOCUMENT TYPE: Patent
 LANGUAGE: Japanese
 FAMILY ACC. NUM. COUNT: 1
 PATENT INFORMATION:

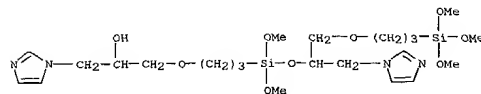
PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 10120690	A2	19980512	JP 1996-280877	19961023
PRIORITY APPL. INFO.:			JP 1996-280877	19961023
OTHER SOURCE(S):		MARPAT 129:16125		

* STRUCTURE DIAGRAM TOO LARGE FOR DISPLAY - AVAILABLE VIA OFFLINE PRINT *

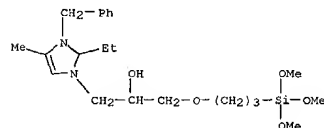
AB The imidazolium salts I (R1 - R3 = H, vinyl, Cl-20 alkyl; R2 and R3 may be bonded to each other forming an aroa ring; R4, R5 = Cl-5 alkyl; R6 = H, Cl-18 (un)substituted alkyl, alkenyl; X = halo, (in)org. acid residue; m = 1-10; n = 1-3), II, III, or IV are prepd. by treatment of imidazoles V with glycidyl compds. VI at 80-200.degree. and quaternization of the resulting products with R6X at 80-200.degree.. Epoxy resins are hardened using .gtoreq.1 selected from I, II, III, and IV and .gtoreq.1 anion acceptors selected from metal, metal carboxylates, metal-acetylacetone complexes, basic oxides, amphoteric oxides, metal carbonates, metal hydrides, and amines. Also claimed are hydrophilic surface treatment agents and antimicrobial agents contg. .gtoreq.1 selected from I, II, III, and IV. 3-Glycidyloxypropyltrimethoxysilane was added dropwise to 2-ethyl-4-methylimidazole at 95.degree. over 30 min and the reaction mixt. was further stirred at 95.degree. for 1 h. Subsequently PhCH2Cl was added dropwise to the reaction mixt. at 140.degree. over 30 min and the reaction mixt. was stirred at 140.degree. for 1 h to give a mixt. of I (R1 = Et, R2 = R4 = Me, R3 = H, R6 = CH2Ph, m = n = 3, X = Cl), II, III, and IV (all variants are same as in I). Gel time of a contg. Epikote 828, the above imidazolium salt mixt., and Zn acetylacetonate was 3 min 33 s, vs. 59 s for a control compn. contg. 2-ethyl-4-methylimidazole as a hardening agent. Coating of an electrodeposited Cu foil with a MeOH soln. of the imidazolium salt mixt. made the surface hydrophilic. An imidazolium salt mixt. similarly prepd. from 2-undecylimidazole instead of 2-ethyl-4-methylimidazole inhibited growth of Aspergillus niger, Cladosporium resinae, etc.
 IT 207732-47-6P 207732-56-7P 207732-60-3P

Kamal Saeed

L3 ANSWER 21 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)
 CN 1H-Imidazole-1-ethanol, .alpha.-[[8-(1H-imidazol-1-ylmethyl)-6,6,14,14-tetramethoxy-2,7,10,15-tetraoxa-6,14-disilahexadec-1-yl]- (9CI) (CA INDEX NAME)



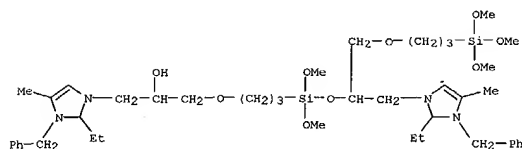
L3 ANSWER 22 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)
 207732-62-5P 207732-66-9P 207732-68-1P
 207732-70-5P 207732-73-6P 207732-75-0P
 207732-77-2P 207732-80-7P 207732-82-9P
 207732-84-1P 207732-88-5P 207732-90-9P
 RL: BAC (Biological activity or effector, except adverse); BSU (Biological study, unclassified); BUU (Biological use, unclassified); IMF (Industrial manufacture); MOA (Modifier or additive use); SPN (Synthetic preparation); TEM (Technical or engineered material use); BIOL (Biological study); PREP (Preparation); USES (Uses) (prepn. of storage-stable silicon-contg. quaternary imidazolium salts as epoxy resin hardeners, hydrophilic coatings, and microbicides)
 RN 207732-47-6 CAPLUS
 CN 1H-Imidazolium, 2-ethyl-1-[2-hydroxy-3-[3-(trimethoxysilyl)propoxy]propyl]-4-methyl-3-(phenylmethyl)-, chloride (9CI) (CA INDEX NAME)



*** FRAGMENT DIAGRAM IS INCOMPLETE ***
 RN 207732-56-7 CAPLUS
 CN 1H-Imidazolium, 2-ethyl-1-[2-[[[3-[3-[2-ethyl-4-methyl-3-(phenylmethyl)-1H-imidazolium-1-yl]-2-hydroxypropoxy]propyl]dimethoxysilyloxy]-3-[3-(trimethoxysilyl)propoxy]propyl]-4-methyl-3-(phenylmethyl)-, dichloride (9CI) (CA INDEX NAME)

09936073 24/09/2003

L3 ANSWER 22 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)

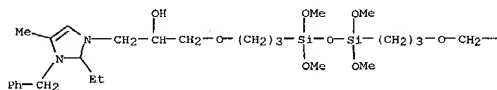


● 2 Cl⁻

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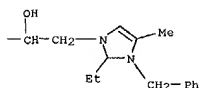
RN 207732-60-3 CAPLUS
CN 1H-imidazolium, 1,1'-bis-[(1,1,3,3-tetramethoxy-1,2-disiloxanediyl)]bis[3,1-propanediyl]bis[2-hydroxy-3,1-propanediyl]bis[2-ethyl-4-methyl-3-(phenylmethyl)-, dichloride (9CI) (CA INDEX NAME)

PAGE 1-A



● 2 Cl⁻

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*** FRAGMENT DIAGRAM IS INCOMPLETE ***

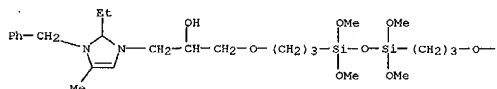
RN 207732-62-5 CAPLUS
CN 1H-imidazolium, 1-[2-hydroxy-3-[3-(trimethoxysilyl)propoxy]propyl]-2-methyl-3-(phenylmethyl)-, chloride (9CI) (CA INDEX NAME)

L3 ANSWER 22 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)

*** FRAGMENT DIAGRAM IS INCOMPLETE ***

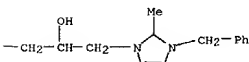
RN 207732-68-1 CAPLUS
CN 1H-imidazolium, 2-ethyl-1-[2-hydroxy-3-[3-[3-[3-[2-hydroxy-3-[2-methyl-3-(phenylmethyl)-1H-imidazolium-1-yl]propoxy]propyl]-1,1,3,3-tetramethoxydisiloxanyl]propoxy]propyl]-4-methyl-3-(phenylmethyl)-, dichloride (9CI) (CA INDEX NAME)

PAGE 1-A



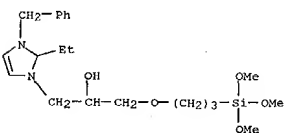
● 2 Cl⁻

PAGE 1-B



*** FRAGMENT DIAGRAM IS INCOMPLETE ***

RN 207732-70-5 CAPLUS
CN 1H-imidazolium, 2-ethyl-1-[2-hydroxy-3-[3-(trimethoxysilyl)propoxy]propyl]-3-(phenylmethyl)-, chloride (9CI) (CA INDEX NAME)



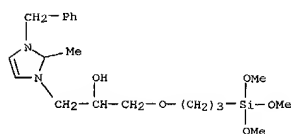
● Cl⁻

*** FRAGMENT DIAGRAM IS INCOMPLETE ***

RN 207732-73-8 CAPLUS
CN 1H-imidazolium, 2-ethyl-1-[10-[[2-ethyl-3-(phenylmethyl)-1H-imidazolium-1-

Kamal Saeed

L3 ANSWER 22 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)

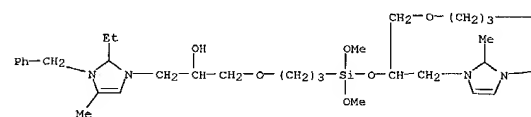


● Cl⁻

*** FRAGMENT DIAGRAM IS INCOMPLETE ***

RN 207732-66-9 CAPLUS
CN 1H-imidazolium, 2-ethyl-1-[2-hydroxy-8,8,16,16-tetramethoxy-10-[[2-methyl-3-(phenylmethyl)-1H-imidazolium-1-yl]methyl]-4,9,12,17-tetraoxa-8,16-disilaooctadec-1-yl]-4-methyl-3-(phenylmethyl)-, dichloride (9CI) (CA INDEX NAME)

PAGE 1-A



● 2 Cl⁻

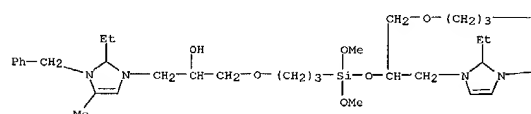
PAGE 1-B



L3 ANSWER 22 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)

yl)methyl]-2-hydroxy-8,8,16,16-tetramethoxy-4,9,12,17-tetraoxa-8,16-disilaooctadec-1-yl]-4-methyl-3-(phenylmethyl)-, dichloride (9CI) (CA INDEX NAME)

PAGE 1-A



● 2 Cl⁻

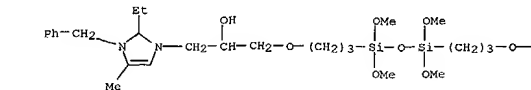
PAGE 1-B



*** FRAGMENT DIAGRAM IS INCOMPLETE ***

RN 207732-75-0 CAPLUS
CN 1H-imidazolium, 2-ethyl-1-[3-[3-[3-[3-[3-[2-ethyl-3-(phenylmethyl)-1H-imidazolium-1-yl]-2-hydroxypropoxy]propyl]-1,1,3,3-tetramethoxydisiloxanyl]propoxy]-2-hydroxypropyl]-4-methyl-3-(phenylmethyl)-, dichloride (9CI) (CA INDEX NAME)

PAGE 1-A

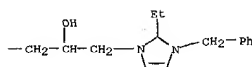


● 2 Cl⁻

09936073 24/09/2003

L3 ANSWER 22 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)

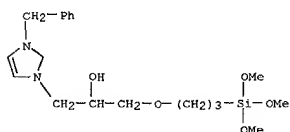
PAGE 1-B



*** FRAGMENT DIAGRAM IS INCOMPLETE ***

RN 207732-77-2 CAPLUS

CN 1H-Imidazolium, 1-[2-hydroxy-3-[3-(trimethoxysilyl)propoxy]propyl]-3-(phenylmethyl)-, chloride (9CI) (CA INDEX NAME)



● 2 Cl⁻

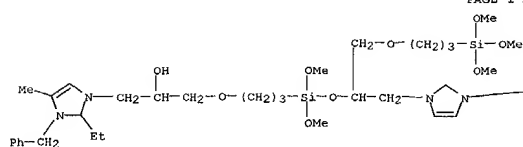
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RN 207732-80-7 CAPLUS

CN 1H-Imidazolium, 2-ethyl-1-[2-hydroxy-8,8,16,16-tetramethoxy-10-[[3-(phenylmethyl)-1H-imidazolium-1-yl]methyl]-4,9,12,17-tetraoxa-8,16-disilaooctadec-1-yl]-4-methyl-3-(phenylmethyl)-, dichloride (9CI) (CA INDEX NAME)

L3 ANSWER 22 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)

PAGE 1-A



● 2 Cl⁻

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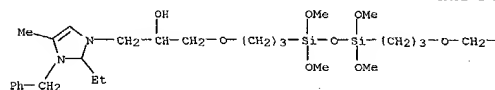
—CH₂—Ph

*** FRAGMENT DIAGRAM IS INCOMPLETE ***

RN 207732-82-9 CAPLUS

CN 1H-Imidazolium, 2-ethyl-1-[2-hydroxy-3-[3-[3-[3-[2-hydroxy-3-[3-(phenylmethyl)-1H-imidazolium-1-yl]propoxy]propyl]-1,1,3,3-tetramethoxydisiloxanyl]propoxy]propyl]-4-methyl-3-(phenylmethyl)-, dichloride (9CI) (CA INDEX NAME)

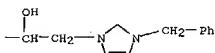
PAGE 1-A



● 2 Cl⁻

L3 ANSWER 22 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)

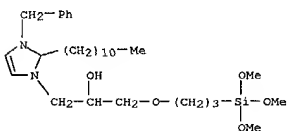
PAGE 1-B



*** FRAGMENT DIAGRAM IS INCOMPLETE ***

RN 207732-84-1 CAPLUS

CN 1H-Imidazolium, 1-[2-hydroxy-3-[3-(trimethoxysilyl)propoxy]propyl]-3-(phenylmethyl)-2-undecyl-, chloride (9CI) (CA INDEX NAME)

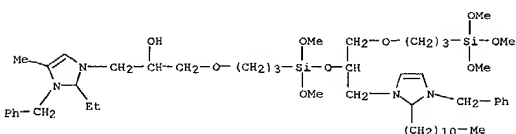


● 2 Cl⁻

*** FRAGMENT DIAGRAM IS INCOMPLETE ***

RN 207732-88-5 CAPLUS

CN 1H-Imidazolium, 2-ethyl-1-[2-hydroxy-8,8,16,16-tetramethoxy-10-[[3-(phenylmethyl)-2-undecyl-1H-imidazolium-1-yl]methyl]-4,9,12,17-tetraoxa-8,16-disilaooctadec-1-yl]-4-methyl-3-(phenylmethyl)-, dichloride (9CI) (CA INDEX NAME)



● 2 Cl⁻

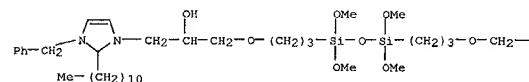
*** FRAGMENT DIAGRAM IS INCOMPLETE ***

RN 207732-90-9 CAPLUS

CN 1H-Imidazolium, 2-ethyl-1-[2-hydroxy-3-[3-[3-[3-[2-hydroxy-3-[3-(phenylmethyl)-1H-imidazolium-1-yl]propoxy]propyl]-1,1,3,3-tetramethoxydisiloxanyl]propoxy]propyl]-4-methyl-3-(phenylmethyl)-, dichloride (9CI) (CA INDEX NAME)

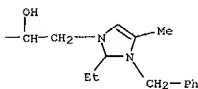
L3 ANSWER 22 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)
(phenylmethyl)-2-undecyl-1H-imidazolium-1-yl]propoxy]propyl]-1,1,3,3-tetramethoxydisiloxanyl]propoxy]propyl]-4-methyl-3-(phenylmethyl)-, dichloride (9CI) (CA INDEX NAME)

PAGE 1-A



● 2 Cl⁻

PAGE 1-B



*** FRAGMENT DIAGRAM IS INCOMPLETE ***

Kamal Saeed

L3 ANSWER 23 OF 33 CAPLUS COPYRIGHT 2003 ACS ON STN
ACCESSION NUMBER: 1998:227419 CAPLUS
DOCUMENT NUMBER: 128:309553
TITLE: Anticorrosive coating compositions for metals
Tsuchita, Katsushi; Kumagaya, Masashi
PATENT ASSIGNEE(S): Japan Energy K. K., Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 13 pp.
CODEN: JKXXX4
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 10095933	A2	19980414	JP 1996-254698	19960926
JP 3386959	B2	20030317		

PRIORITY APPLN. INFO.: JP 1996-254698 19960926

AB The compns. with improved adhesion contain sillicic acid and optionally g.tored.1 organosilicon compds. selected from R1Si(OR)2nR3-n-3, R4Si(OR)2nR3-n-3, and Si(OR)4 [R1 = hydrocarbyl substituted by epoxy, vinyl, (meth)acrylic, amino, S, Si, imidazole, halo, OH, and/or styryl group, may contain ether or ester link; R2, R3 = Cl-5 alkyl, may contain ether link n = 1-3; R4 = R5(O)xCOC(R5)O2Oly(CH2)n; m = 2-10; x, y = 0-1; R5 = Cl-5 alkyl; R6 = H, Cl-5 alkyl, R7(O)2COO; z = 0-1; R7 = hydrocarbyl, may contain Si(OR)2nR3-n-3; R8 = Cl-5 alkyl. Corrosion-resistant metals coated with the compns. and optionally further coated with the organosilicon compds. are also claimed. Thus, adding dropwise a Na metasilicate soln. in THF, saltiing-out by NaCl, dehydrating the THF phase, and filtering gave a 18.6 g/L sillicic acid/THF soln. A Zn-coated steel sheet (Zinkote) was degreased, coated with the THF soln. contg. 60 g/L (3-methacryloyloxypropyl)trimethoxysilane, and heated to give a test piece showing no corrosion in a salt spray test and good adhesion to a melamine-alkyd resin top coat.

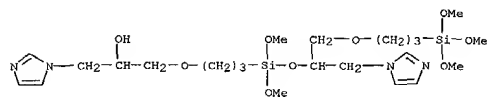
IT	205812-05-1F	Industrial resin cop. etc.
RI	IMF (Industrial manufacture); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)	
		(silicic acid copolymer-based anticorrosive coatings for metals with good adhesion to top coatings)
RN	205812-05-1	CAPUS
CN	Silicic acid (H2SiO3), polymer with 1-[(2,2-dimethoxy-1,6-dioxo-2-silylcyclooct-8-yl)methyl]-1H-imidazole, .alpha.-[8-(1H-imidazol-1-yl)methyl]-6,6,14,14-tetraethoxy-2,7,10,15-tetraoxa-6,14-disilohexadec-1-yl]-1H-imidazole-1-ethanol and .alpha.-[13-(trimethoxysilyl)propoxymethyl]-1H-imidazole-1-ethanol	
		1-H[imidazol-1-yl]ethyl; 19GCU (CA_INDEX NAME)

CM 1

CRN 149394-84-3

CMF C23 H44 N4 O9 Si2

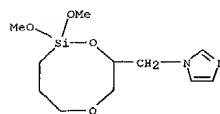
L3 ANSWER 23 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)



CM 2

CBN 149394-77-4

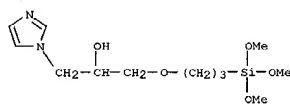
CRN 149394-77-4
CMF C11 H20 N2 O4 Si



CM 3

CPN 149394-70-7

CRN 149394-70-7
CME C12 H34 N3 O6 S;



CM 4

CBN 7699-41-4

CRN 7699-41-
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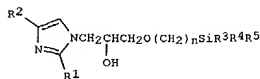


L3 ANSWER 23 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)

L3 ANSWER 24 OF 33 CAPLUS COPYRIGHT 2003 ACS ON STN
 ACCESSION NUMBER: 1997:496237 CAPLUS
 DOCUMENT NUMBER: 127:116220
 TITLE: Electrically conductive paste using
 imidazolized nickel copper powders
 INVENTOR(S): Sasaki, Akihiro; Hirai, Keizo; Wada, Hiroshi
 PATENT ASSIGNEE(S): Hitachi Chemical Co., Ltd., Japan
 SOURCE: Jpn. Kokai Tokkyo Koho, 5 pp.
 CODEN: JKXXXX
 DOCUMENT TYPE: Patent
 LANGUAGE: Japanese
 FAMILY ACC. NUM. COUNT: 1
 PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 09180542	A2	19970711	JP 1995-337227	19951225
PRIORITY APPLN. INFO.:			JP 1995-337227	19951225

OTHER SOURCE(S): MARPAT 127:116220
GI

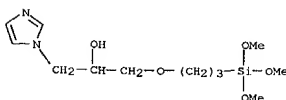


AB The conductive paste consists of (Ag-plated) Cu powders having av. diam. $\geq 0.30 \mu\text{m}$, coated with the imidazolesilane compd. I (antioxidant: R1-2 = H, alkyl, Ph, CN; R3-5 = H, alkyl, alkoxy; n = 1-5) in 0.0001-5

to the Cu powders and dispersed in an org. solvent contg. a thermosetting resin (adhesive: e.g., phenolic resin, epoxy resin). The Cu powders preferably have a flake or dendritic shape for improved cond. The conductive paste, using the inexpensive materials, has good cond. even under high moisture.

IT 149394-70-7, IS 1000
RL: TEM (Technical or engineered material use); USES (Uses)
(coating; elec. conductive paste using copper powders coated with
imidazole silane for oxidn. resistance)

RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy)methyl]-
(9CI) (CA INDEX NAME)



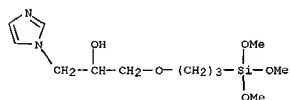
09936073 24/09/2003

L3 ANSWER 25 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
 ACCESSION NUMBER: 1997:475603 CAPLUS
 DOCUMENT NUMBER: 127:149806
 TITLE: Surface-treated fillers and polymer compositions
 using
 them
 INVENTOR(S): Akutsu, Yoshinori; Kumagai, Masashi
 PATENT ASSIGNEE(S): Japan Energy K. K., Japan
 SOURCE: Jpn. Kokai Tokkyo Koho, 7 pp.
 CODEN: JKXXAF
 DOCUMENT TYPE: Patent
 LANGUAGE: Japanese
 FAMILY ACC. NUM. COUNT: 1
 PATENT INFORMATION:
 PATENT NO. KIND DATE APPLICATION NO. DATE
 JP 09169871 A2 19970630 JP 1995-332035 19951220
 PRIORITY APPLN. INFO.: JP 1995-332035 19951220
 GI

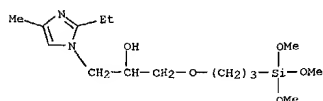
* STRUCTURE DIAGRAM TOO LARGE FOR DISPLAY - AVAILABLE VIA OFFLINE PRINT *

AB Title fillers are surface-treated with imidazole silanes of I, II, III,
 or
 their mixts. (R1 = H, vinyl, Cl-5 alkyl; R2 = H, Cl-20 alkyl; R3, R4 =
 Cl-3 alkyl; n = 1-3). Polymer compns. comprising above fillers show good
 mech. strength and durability and are useful for elec. and electronic
 parts, adhesives, coatings, composites, etc. Thus, 100 parts ST 7
 (silica) was mixed with a soln. (pH = 5) contg. 2 parts I-II-III
 (45:22:33) mixt. (R1 = R2 = H; R3 = Me; n = 3), 100 parts H2O-EtOH (1:1)
 mixt., and HCl, stirred one whole day and night, filtered, washed, and
 dried to give a surface-treated filler, 100 parts of which was mixed with
 Epikote 828 100, AH 154 (dicyandiamide) 5, and 2E4MZ (2-ethyl-4-
 methylimidazole) 1 part, poured into a mold, and cured to give a molding
 with good initial bending strength 107 N/mm2 (JIS K 6911).
 IT 149394-70-7 149394-84-3
 RL: MOA (Modifier or additive use); PEP (Physical, engineering or
 chemical
 process); PROC (Process); USES (Uses)
 (imidazole silane surface-treated fillers for polymer compns. with
 good mech. strength and durability)
 RN 149394-70-7 CAPLUS
 CN 1H-Imidazole-1-ethanol, .alpha.-[3-(trimethoxysilyl)propoxy)methyl]-
 (9CI) (CA INDEX NAME)

L3 ANSWER 26 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
 ACCESSION NUMBER: 1997:416261 CAPLUS
 DOCUMENT NUMBER: 127:58030
 TITLE: Solder resist composition containing silane compound
 with imidazole group
 INVENTOR(S): Kodama, Yukio; Shosmi, Shigeo; Kubota, Hiroyuki
 PATENT ASSIGNEE(S): Toyo Ink Mfg. Co., Ltd., Japan
 SOURCE: Jpn. Kokai Tokkyo Koho, 10 pp.
 CODEN: JKXXAF
 DOCUMENT TYPE: Patent
 LANGUAGE: Japanese
 FAMILY ACC. NUM. COUNT: 1
 PATENT INFORMATION:
 PATENT NO. KIND DATE APPLICATION NO. DATE
 JP 09114096 A2 19970502 JP 1995-266575 19951016
 PRIORITY APPLN. INFO.: JP 1995-266575 19951016
 AB The compn. contains an active ray-curable resin and a silane compd. with
 an imidazole group. The compn. shows good adhesion with Cu, good
 resistance to plating, chems., alkalis, solvents, and water.
 IT 149394-70-7, IS 1000 149394-73-0 149394-76-3
 RL: MOA (Modifier or additive use); TEM (Technical or engineered material
 use); USES (Uses)
 (solder resist compn. contg. curable resin and silane compd. with
 imidazole group)
 RN 149394-70-7 CAPLUS
 CN 1H-Imidazole-1-ethanol, .alpha.-[3-(trimethoxysilyl)propoxy)methyl]-
 (9CI) (CA INDEX NAME)

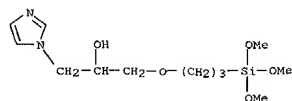


RN 149394-73-0 CAPLUS
 CN 1H-Imidazole-1-ethanol, 2-ethyl-4-methyl-.alpha.-[3-(trimethoxysilyl)propoxy)methyl]- (9CI) (CA INDEX NAME)

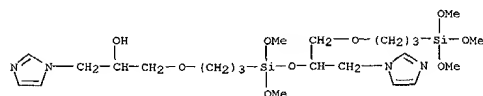


RN 149394-76-3 CAPLUS
 CN 1H-Imidazole-1-ethanol, 4-ethenyl-.alpha.-[3-(trimethoxysilyl)propoxy)methyl]- (9CI) (CA INDEX NAME)

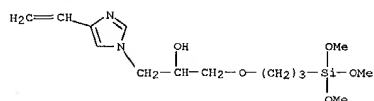
L3 ANSWER 25 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)



RN 149394-84-3 CAPLUS
 CN 1H-imidazole-1-ethanol, .alpha.-[6-(1H-imidazol-1-ylmethyl)-6,6,14,14-tetramethoxy-2,7,10,15-tetraoxa-6,14-disilaheptadec-1-yl]- (9CI) (CA INDEX NAME)



L3 ANSWER 26 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)



Kamal Saeed

09936073 24/09/2003

L3 ANSWER 27 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
 ACCESSION NUMBER: 1997:281228 CAPLUS
 DOCUMENT NUMBER: 126:270385
 TITLE: Photosolder resist composition containing inorganic filler treated with silane coupling agents
 INVENTOR(S): Kubota, Hiroyuki
 PATENT ASSIGNEE(S): Toyo Ink Mfg Co, Japan
 SOURCE: Jpn. Kokai Tokkyo Koho, 11 pp.
 CODEN: JKXXAF
 DOCUMENT TYPE: Patent
 LANGUAGE: Japanese
 FAMILY ACC. NUM. COUNT: 1
 PATENT INFORMATION:

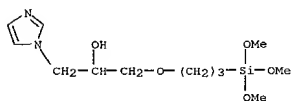
PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 09043846	A2	19970214	JP 1995-266576	19951016

PRIORITY APPLN. INFO.: JP 1995-126177 19950525

AB The compn. contains (A) an active energy ray-curable resin having carboxy group and alc. hydroxy group and (B) an inorg. filler pretreated with a silane coupling agent. The resist compn. shows good adhesion to Cu and durability.

IT 149394-70-7, IS 1000
 RL: MOA (Modifier or additive use); USES (Uses)
 (IS 1000: photosolder resist compn. contg. inorg. filler treated with silane coupling agents to improve adhesion and durability)

RN 149394-70-7 CAPLUS
 CN 1H-Imidazole-1-ethanol, .alpha.-[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



L3 ANSWER 28 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
 ACCESSION NUMBER: 1997:203691 CAPLUS
 DOCUMENT NUMBER: 126:200218
 TITLE: Epoxy resin adhesive compositions and imidazole silanes for the compositions
 INVENTOR(S): Akutsu, Yoshinori; Tsuchida, Katsuyuki; Kumagai, Masashi
 PATENT ASSIGNEE(S): Japan Enajii Kk, Japan
 SOURCE: Jpn. Kokai Tokkyo Koho, 9 pp.
 CODEN: JKXXAF
 DOCUMENT TYPE: patent
 LANGUAGE: Japanese
 FAMILY ACC. NUM. COUNT: 1
 PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 09012683	A2	19970114	JP 1995-168669	19950704
JP 3396562	B2	20030414		

PRIORITY APPLN. INFO.: JP 1995-168669 19950704

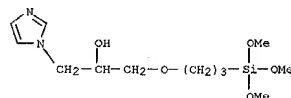
* STRUCTURE DIAGRAM TOO LARGE FOR DISPLAY - AVAILABLE VIA OFFLINE PRINT *

AB The compns., having good adhesion, comprise epoxy resin compns. contg. I, II, and/or III (R1 = H, vinyl, Cl-5 alkyl; R2 = H, Cl-20 alkyl; R3-4 = Cl-3 alkyl; n = 1-3). Thus, an adhesive having shear strength (for bonding of stainless steel plates) 1.31 KN/cm2 was prepd. from Epikote

828 contg. 45:22-33 I, II and III mixt. (R1 = R2 = H; R3 = Me; n = 3) 1, AH 154 (dicyandiamide) 5 and 2-ethyl-4-methylimidazole 1 phr.

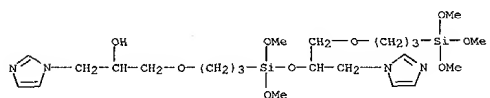
IT 149394-70-7 149394-84-3 187463-05-4
 187463-07-6
 RL: MOA (Modifier or additive use); USES (Uses)
 (epoxy resin adhesive compns. and imidazole silanes for the compns.)

RN 149394-70-7 CAPLUS
 CN 1H-Imidazole-1-ethanol, .alpha.-[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)

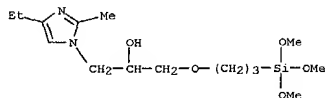


RN 149394-84-3 CAPLUS
 CN 1H-Imidazole-1-ethanol, .alpha.-[8-(1H-imidazol-1-ylmethyl)-6,6,14,14-tetramethoxy-2,7,10,15-tetraoxa-6,14-disilahehexadec-1-yl]- (9CI) (CA INDEX NAME)

L3 ANSWER 28 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)
 NAME)

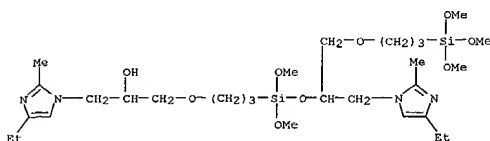


RN 187463-05-4 CAPLUS
 CN 1H-Imidazole-1-ethanol, 4-ethyl-2-methyl-.alpha.-[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



RN 187463-07-6 CAPLUS
 CN 1H-Imidazole-1-ethanol, 4-ethyl-.alpha.-[8-(4-ethyl-2-methyl-1H-imidazol-

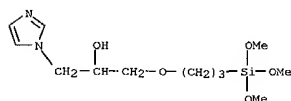
1-yl)methyl]-6,6,14,14-tetramethoxy-2,7,10,15-tetraoxa-6,14-disilahehexadec-1-yl]-2-methyl- (9CI) (CA INDEX NAME)



L3 ANSWER 29 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
 ACCESSION NUMBER: 1996:312284 CAPLUS
 DOCUMENT NUMBER: 125:223406
 TITLE: The application of imidazolsilane to epoxy resin
 AUTHOR(S): Akutsu, Yoshinori; Kumagai, Masashi
 CORPORATE SOURCE: Mats. & Components Lab., Japan Energy Corp., Japan
 SOURCE: Koen Yoshishu - Nippon Setchaku Gakkai Nenji Taikai (1996), 34th, 99-100
 CODEN: KYNTFX
 PUBLISHER: Nippon Setchaku Gakkai
 DOCUMENT TYPE: Journal
 LANGUAGE: Japanese
 AB A new silane coupling agent was synthesized which has an imidazole group for promoting the epoxy resin curing.

IT 149394-70-7
 RL: CAT (Catalyst use); USES (Uses)
 (application of imidazolsilane to epoxy resin)

RN 149394-70-7 CAPLUS
 CN 1H-Imidazole-1-ethanol, .alpha.-[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)

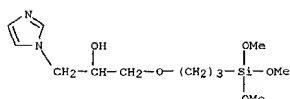


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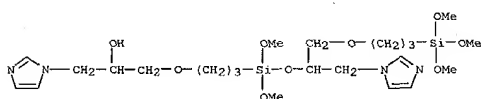
L3 ANSWER 30 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
 ACCESSION NUMBER: 1996:321194 CAPLUS
 DOCUMENT NUMBER: 125:12409
 TITLE: Copper-containing electroconductive materials and resin compositions
 INVENTOR(S): Yoshida, Tomohito; Mukai, Yutaka
 PATENT ASSIGNEE(S): Japan Enajii Kk, Japan
 SOURCE: Jpn. Kokai Tokkyo Koho, 6 pp.
 CODEN: JKXXAF
 DOCUMENT TYPE: Patent
 LANGUAGE: Japanese
 FAMILY ACC. NUM. COUNT: 1
 PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 08048816	A2	19960220	JP 1994-319447	19941130
PRIORITY APPLN. INFO.:			JP 1994-43335	19940218
			JP 1994-144121	19940603

OTHER SOURCE(S): MARPAT 125:12409
 AB The title compns., which have antistatic and electromagnetic wave-shielding properties, contain Cu-type electroconductive materials treated with imidazole silanes and titanate coupling agents. Thus, a pellet prep. from 4700 JG (polypropylene) 79.7, CDA 6 [(2-HOC6H4CONHNHCO(CH2)5)2] 0.3, and carbon fibers 20 parts, which was plated with Cu, impregnated with ZCH2CH(OH)CH2O(CH2)3Si(OMe)3 (Z = imidazolyl), and sprayed with a titanate (KR-TTS), showed surface resistivity 6.6 times. 10⁻² .OMEGA./box..
 IT 149394-70-7
 RI: MOA (Modifier or additive use); USES (Uses)
 (antistatic and electromagnetic-shielding resin compns. contg. copper treated with imidazole silane and titanate coupling agent)
 RN 149394-70-7 CAPLUS
 CN 1H-imidazole-1-ethanol, .alpha.-[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



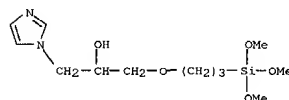
L3 ANSWER 31 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)
 RN 149394-84-3 CAPLUS
 CN 1H-imidazole-1-ethanol, .alpha.-[8-(1H-imidazol-1-ylmethyl)-6,6,14,14-tetramethoxy-2,7,10,15-tetraoxa-6,14-disilahehexadec-1-yl]- (9CI) (CA INDEX NAME)



L3 ANSWER 31 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
 ACCESSION NUMBER: 1996:82920 CAPLUS
 DOCUMENT NUMBER: 124:148341
 TITLE: Surface treating agents for copper foils and their copper clad laminates
 INVENTOR(S): Tsuchida, Katsuyuki; Kumagai, Masashi; Sasa, Naruaki;
 Akase, Fumiaki; Ogino, Yukio
 PATENT ASSIGNEE(S): Japan Enajii K. K., Japan
 SOURCE: Jpn. Kokai Tokkyo Koho, 6 pp.
 CODEN: JKXXAF
 DOCUMENT TYPE: Patent
 LANGUAGE: Japanese
 FAMILY ACC. NUM. COUNT: 1
 PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 07286160	A2	19951031	JP 1994-81541	19940420
PRIORITY APPLN. INFO.:			JP 1994-24142	19940222

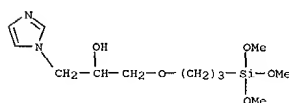
AB The title treatment agents which improve adhesion of Cu foils and prepregs and solder heat resistance contain (A) trifunctional silanes YSiX3 (Y = org. functional group, hydrocarbon group contg. org. functional groups and optionally ether bond; X = hydrolyzable group) and (B) tetrafunctional silanes Si(OR)4 (R = hydrocarbon group which may contain ether bond).
 The title Cu clad laminate are composed of Cu foils with layers of the treatment agents and prepregs, which may be bonded via adhesive layers. Thus, electrolytic Cu foil was treated with copper pyrite on the rough side, plated with Zn or Zn-Cr oxide, and coated with a AcOH soln. with pH 5 contg. 0.2% 3-glycidoxypropyltrimethoxysilane and 0.2% tetraethoxysilane and dried at 100.degree. to give a foil, which was press-heated with a glass-epoxy resin prepreg, etched on the Cu foil side, and immersed in boiling water to show improved adhesion.
 IT 149394-70-7 149394-84-3
 RI: MOA (Modifier or additive use); USES (Uses)
 (silane surface treating agents for Cu foils and Cu clad laminates with boiling water resistance and adhesion)
 RN 149394-70-7 CAPLUS
 CN 1H-imidazole-1-ethanol, .alpha.-[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



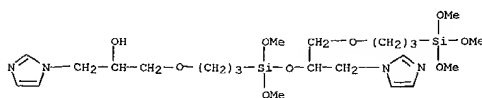
L3 ANSWER 32 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
 ACCESSION NUMBER: 1995:480174 CAPLUS
 DOCUMENT NUMBER: 122:216756
 TITLE: Silicon compound-based metal surface treating agents
 INVENTOR(S): Tsuchida, Katsuyuki; Kumagai, Masashi; Ogino, Yukio
 PATENT ASSIGNEE(S): Japan Enajii Kk, Japan
 SOURCE: Jpn. Kokai Tokkyo Koho, 8 pp.
 CODEN: JKXXAF
 DOCUMENT TYPE: Patent
 LANGUAGE: Japanese
 FAMILY ACC. NUM. COUNT: 1
 PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 06177535	A2	19940624	JP 1992-329304	19921209
PRIORITY APPLN. INFO.:			JP 1992-329304	19921209

OTHER SOURCE(S): MARPAT 122:216756
 AB The title agents, giving good corrosion preventing and modified adhesion properties to metal surface, e.g., of Cu foils for printed circuit boards, comprise imidazole-contg. silane derivs. (e.g., reaction products of imidazole derivs. and 3-glycidoxypropyltrimethoxysilane) and bis(trialkoxysilyl) compds. [e.g., 1,2-bis(trimethoxysilyl)ethane].
 IT 149394-70-7 149394-84-3
 RI: PEP (Physical, engineering or chemical process); PRP (Properties); PROC (Process)
 (silicon compd.-based metal surface treating agents)
 RN 149394-70-7 CAPLUS
 CN 1H-imidazole-1-ethanol, .alpha.-[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



RN 149394-84-3 CAPLUS
 CN 1H-imidazole-1-ethanol, .alpha.-[8-(1H-imidazol-1-ylmethyl)-6,6,14,14-tetramethoxy-2,7,10,15-tetraoxa-6,14-disilahehexadec-1-yl]- (9CI) (CA INDEX NAME)



09936073 24/09/2003

L3 ANSWER 33 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
 ACCESSION NUMBER: 1993:507499 CAPLUS
 DOCUMENT NUMBER: 119:107499
 TITLE: Imidazole-silane compounds, their production and metal
 INVENTOR(S): surface finishing agent containing them
 PATENT ASSIGNEE(S): Tsuchida, Katsuyuki; Kumagai, Masahi; Ogino, Yukio
 SOURCE: Nippon Mining Co. Ltd., Japan
 Eur. Pat. Appl., 22 pp.
 CODEN: EPXXDW
 DOCUMENT TYPE: Patent
 LANGUAGE: English
 FAMILY ACC. NUM. COUNT: 1
 PATENT INFORMATION:

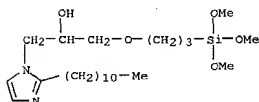
PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
EP 526847	A1	19930210	EP 1992-113067	19920731
R: DE, FR, GB				
JP 05186479	A2	19930727	JP 1992-183783	19920710
JP 07068256	B4	19950726		
US 5258522	A	19931102	US 1992-518454	19920722
PRIORITY APPLN. INFO.:			JP 1991-214181	19910801
			JP 1992-183783	19920710

AB Described is a novel imidazole-silane compd. which has an excellent heat resistance and a high corrosion preventive effect on a metal surface and is capable of remarkably improving the adhesion of a metal to a resin substrate, a process for prep. such a compd., and a new metal surface finishing agent comprising the same. The novel imidazole-silane compd.

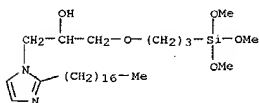
is produced by reacting an imidazole compd. with a 3-glycidoxypropylsilane compd. at 80 to 200.degree.. The surface finishing agents are used for copper foils for laminates for printed circuits.

IT 149394-70-7P 149394-71-8P 149394-72-9P
 149394-73-0P 149394-74-1P 149394-75-2P
 149394-76-3P 149394-84-3P 149394-85-4P
 149394-86-5P 149394-87-6P 149394-88-7P
 149394-89-8P 149394-90-1P 149394-91-2P
 149394-92-3P 149394-93-4P 149394-97-8P
 149394-98-9P 149394-99-0P 149395-00-6P
 149395-01-7P 149395-02-8P 149395-03-9P
 149395-08-4P 149395-09-5P 149395-10-6P
 149395-11-9P 149395-12-0P 149395-13-1P
 149395-14-2P 149395-18-6P 149395-19-7P
 149395-20-0P
 RI: PREP (Preparation)
 (prepn. of, as metal surface finishing agents)
 RN 149394-70-7 CAPLUS
 CN 1H-Imidazole-1-ethanol, .alpha.-[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)

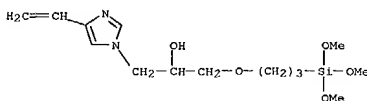
L3 ANSWER 33 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)
 CN 1H-Imidazole-1-ethanol, .alpha.-[3-(trimethoxysilyl)propoxy]methyl]-2-undecyl- (9CI) (CA INDEX NAME)



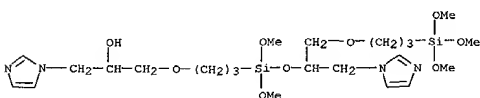
RN 149394-75-2 CAPLUS
 CN 1H-Imidazole-1-ethanol, 2-heptadecyl-.alpha.-[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



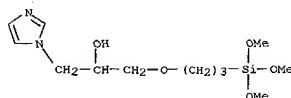
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 CN 1H-Imidazole-1-ethanol, 4-ethenyl-.alpha.-[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



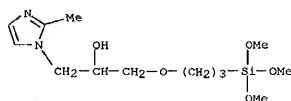
RN 149394-84-3 CAPLUS
 CN 1H-Imidazole-1-ethanol, .alpha.-[8-(1H-imidazol-1-ylmethyl)-6,6,14,14-tetramethoxy-2,7,10,15-tetraoxa-6,14-disiladecadec-1-yl]- (9CI) (CA INDEX NAME)



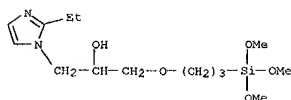
L3 ANSWER 33 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)



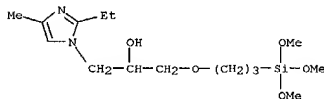
RN 149394-71-8 CAPLUS
 CN 1H-Imidazole-1-ethanol, 2-methyl-.alpha.-[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



RN 149394-72-9 CAPLUS
 CN 1H-Imidazole-1-ethanol, 2-ethyl-.alpha.-[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)

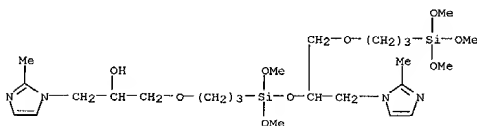


RN 149394-73-0 CAPLUS
 CN 1H-Imidazole-1-ethanol, 2-ethyl-4-methyl-.alpha.-[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)

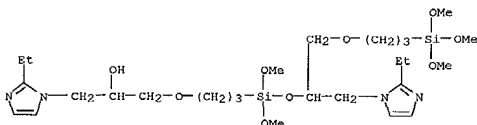


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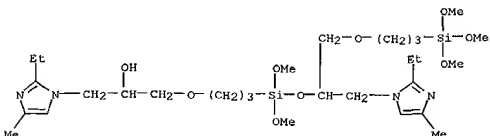
L3 ANSWER 33 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)
 RN 149394-85-4 CAPLUS
 CN 1H-Imidazole-1-ethanol, 2-methyl-.alpha.-[6,6,14,14-tetramethoxy-8-[(2-methyl-1H-imidazol-1-yl)methyl]-2,7,10,15-tetraoxa-6,14-disiladecadec-1-yl]- (9CI) (CA INDEX NAME)



RN 149394-86-5 CAPLUS
 CN 1H-Imidazole-1-ethanol, 2-ethyl-.alpha.-[8-[(2-ethyl-1H-imidazol-1-yl)methyl]-6,6,14,14-tetramethoxy-2,7,10,15-tetraoxa-6,14-disiladecadec-1-yl]- (9CI) (CA INDEX NAME)



RN 149394-87-6 CAPLUS
 CN 1H-Imidazole-1-ethanol, 2-ethyl-.alpha.-[8-[(2-ethyl-4-methyl-1H-imidazol-1-yl)methyl]-6,6,14,14-tetramethoxy-2,7,10,15-tetraoxa-6,14-disiladecadec-1-yl]-4-methyl- (9CI) (CA INDEX NAME)

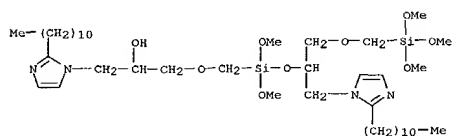


RN 149394-88-7 CAPLUS
 CN 1H-Imidazole-1-ethanol, .alpha.-[4,4,10,10-tetramethoxy-6-[(2-undecyl-1H-imidazol-1-yl)methyl]-2,5,8,11-tetraoxa-4,10-disiladodec-1-yl]-2-undecyl- (9CI) (CA INDEX NAME)

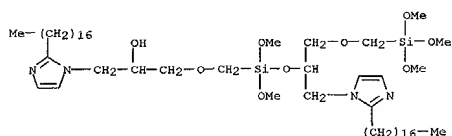
Kamal Saeed

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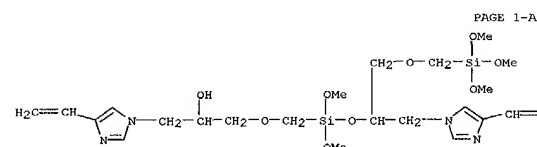
L3 ANSWER 33 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)



RN 149394-89-8 CAPLUS
CN 1H-Imidazole-1-ethanol, 2-heptadecyl-.alpha.-[6-[(2-heptadecyl-1H-imidazol-1-yl)methyl]-4,10,10-tetramethoxy-2,5,8,11-tetraoxa-4,10-disiladodec-1-yl]- (9CI) (CA INDEX NAME)

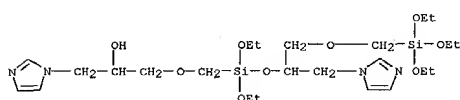


RN 149394-90-1 CAPLUS
CN 1H-Imidazole-1-ethanol, 4-ethenyl-.alpha.-[6-[(4-ethenyl-1H-imidazol-1-yl)methyl]-4,10,10-tetramethoxy-2,5,8,11-tetraoxa-4,10-disiladodec-1-yl]- (9CI) (CA INDEX NAME)

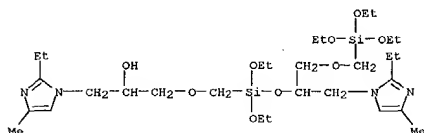


L3 ANSWER 33 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)

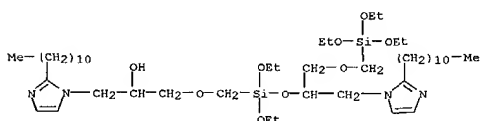
RN 149394-97-8 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[4,4,10,10-tetraethoxy-6-(1H-imidazol-1-yl)methyl]-2,5,8,11-tetraoxa-4,10-disiladodec-1-yl]- (9CI) (CA INDEX NAME)



RN 149394-96-9 CAPLUS
CN 1H-Imidazole-1-ethanol, 2-ethyl-4-methyl-.alpha.-[4,4,10,10-tetraethoxy-6-(2-ethyl-4-methyl-1H-imidazol-1-yl)methyl]-2,5,8,11-tetraoxa-4,10-disiladodec-1-yl]- (9CI) (CA INDEX NAME)



RN 149394-99-0 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[4,4,10,10-tetraethoxy-6-(2-undecyl-1H-imidazol-1-yl)methyl]-2,5,8,11-tetraoxa-4,10-disiladodec-1-yl]-2-undecyl- (9CI) (CA INDEX NAME)



RN 149395-00-6 CAPLUS
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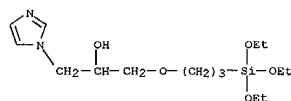
Kamal Saeed

L3 ANSWER 33 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)

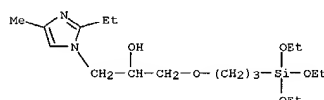
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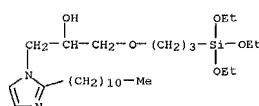
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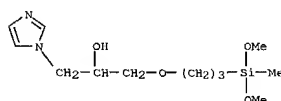
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CN 1H-Imidazole-1-ethanol, 2-ethyl-4-methyl-.alpha.-[3-(triethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



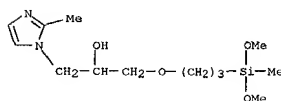
RN 149394-93-4 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[3-(triethoxysilyl)propoxy]methyl]-2-undecyl- (9CI) (CA INDEX NAME)



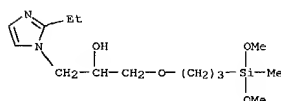
L3 ANSWER 33 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)



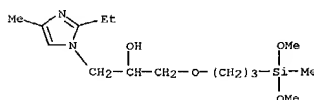
RN 149395-01-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[3-(dimethoxymethylsilyl)propoxy]methyl]-2-methyl- (9CI) (CA INDEX NAME)



RN 149395-02-8 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[3-(dimethoxymethylsilyl)propoxy]methyl]-2-ethyl- (9CI) (CA INDEX NAME)



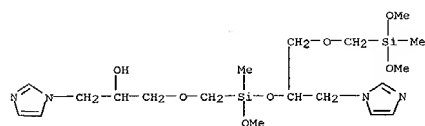
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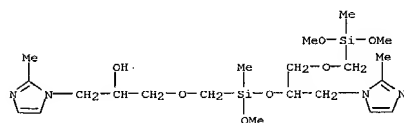
RN 149395-08-4 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[6-(1H-imidazol-1-ylmethyl)-4,10-dimethoxy-4,10-dimethyl-2,5,8,11-tetraoxa-4,10-disiladodec-1-yl]- (9CI) (CA INDEX NAME)

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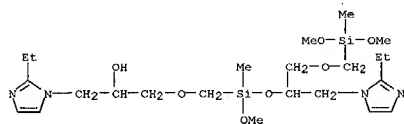
L3 ANSWER 33 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)
(NAME)



RN 149395-09-5 CAPLUS
CN 1H-Imidazole-1-ethanol,
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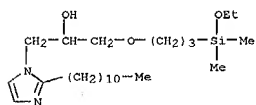


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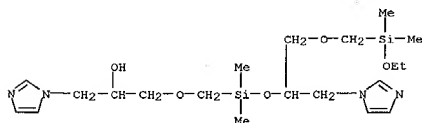


RN 149395-11-9 CAPLUS
CN 1H-Imidazole-1-ethanol,
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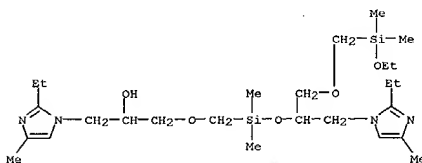
L3 ANSWER 33 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)



RN 149395-18-6 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[6-[(1H-imidazol-1-yl)methyl]-4,4,10,10-
tetramethyl-2,5,8,11-tetraoxa-4,10-disilatridec-1-yl]- (9CI) (CA INDEX
NAME)

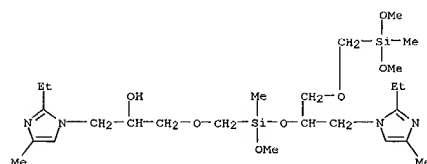


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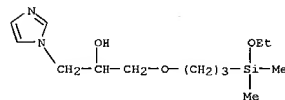


RN 149395-20-0 CAPLUS
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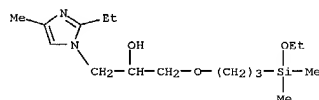
L3 ANSWER 33 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)
disiladodec-1-yl]-4-methyl- (9CI) (CA INDEX NAME)



RN 149395-12-0 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[3-[(ethoxydimethylsilyl)propoxy]methyl]-
(9CI) (CA INDEX NAME)

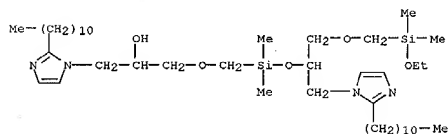


RN 149395-13-1 CAPLUS
CN 1H-Imidazole-1-ethanol,
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ethyl-4-methyl- (9CI) (CA INDEX NAME)



RN 149395-14-2 CAPLUS
CN 1H-Imidazole-1-ethanol,
.alpha.-[3-[(ethoxydimethylsilyl)propoxy]methyl]-2-
undecyl- (9CI) (CA INDEX NAME)

L3 ANSWER 33 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)



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=> FIL STNGUIDE

COST IN U.S. DOLLARS

SINCE FILE	TOTAL
ENTRY	SESSION
153.44	301.80

FULL ESTIMATED COST

DISCOUNT AMOUNTS (FOR QUALIFYING ACCOUNTS)

SINCE FILE	TOTAL
ENTRY	SESSION
-21.48	-21.48

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FILE 'STNGUIDE' ENTERED AT 08:27:29 ON 24 SEP 2003

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FILE CONTAINS CURRENT INFORMATION.

LAST RELOADED: Sep 19, 2003 (20030919/UP).

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ALL L# QUERIES AND ANSWER SETS ARE DELETED AT LOGOFF

LOGOFF? (Y)/N/HOLD:y

COST IN U.S. DOLLARS

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ENTRY	SESSION
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FULL ESTIMATED COST

DISCOUNT AMOUNTS (FOR QUALIFYING ACCOUNTS)

SINCE FILE	TOTAL
ENTRY	SESSION
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CA SUBSCRIBER PRICE

STN INTERNATIONAL LOGOFF AT 08:28:38 ON 24 SEP 2003